



**THE DATASHEET OF
MIMXRT1015CAF4A**





MIMXRT1015CAF4A MIMXRT1015CAF4B

i.MX RT1015 Crossover Processors Data Sheet for Industrial Products



Package Information
Plastic Package
100-Pin LQFP, 14 x 14 mm, 0.5 mm pitch

| |
|---------------------------------------|
| Ordering Information |
| See Table 1 on page 5 |

1 i.MX RT1015 introduction

The i.MX RT1015 is a processor of i.MX RT family featuring NXP’s advanced implementation of the Arm® Cortex®-M7 core, which operates at speeds up to 396 MHz to provide high CPU performance and real-time response.

The i.MX RT1015 processor has 128 KB on-chip RAM, which can be flexibly configured as TCM or general-purpose on-chip RAM. The i.MX RT1015 integrates advanced power management module with DCDC and LDO that reduces complexity of external power supply and simplifies power sequencing. The i.MX RT1015 also provides various memory interfaces, including Quad SPI, and a wide range of connectivity interfaces including UART, SPI, I2C, and USB; for connecting peripherals including Bluetooth™, and GPS. The i.MX RT1015 also has rich audio features, including SPDIF and I2S audio interface. Various analog IP integration, including ADC, temperature sensor, etc.

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The i.MX RT1015 is specifically useful for applications such as:

- Industrial
- Motor Control
- Home Appliance
- Audio
- IoT

1.1 Features

The i.MX RT1015 processors are based on Arm Cortex-M7 Core™ Platform, which has the following features:

- Supports single Arm Cortex-M7 with:
 - 16 KB L1 Instruction Cache
 - 16 KB L1 Data Cache
 - Full featured Floating Point Unit (FPU) with support of the VFPv5 architecture
 - Support the Armv7-M Thumb instruction set
- Integrated MPU, up to 16 individual protection regions
- Up to 128 KB I-TCM and D-TCM in total
- Frequency of 396 MHz
- Cortex M7 CoreSight™ components integration for debug
- Frequency of the core, as per [Table 9, "Operating ranges," on page 17](#).

The SoC-level memory system consists of the following additional components:

- Boot ROM (96 KB)
- On-chip RAM (128 KB)
 - Configurable RAM size up to 128 KB shared with CM7 TCM
- External memory interfaces:
 - SPI NOR/NAND FLASH
 - Parallel NOR FLASH with XIP support
 - Single/Dual channel Quad SPI FLASH with XIP support
- Timers and PWMs:
 - Two General Programmable Timers
 - 4-channel generic 32-bit resolution timer
 - Each support standard capture and compare operation
 - Four Periodical Interrupt Timers
 - Generic 32-bit resolution timer
 - Periodical interrupt generation
 - One Quad Timer
 - 4-channel generic 16-bit resolution timer

- Each support standard capture and compare operation
- Quadrature decoder integrated
- One FlexPWM
 - Up to 8 individual PWM channels
 - 16-bit resolution PWM suitable for Motor Control applications
- One Quadrature Encoder/Decoder

Each i.MX RT1015 processor enables the following interfaces to external devices (some of them are muxed and not available simultaneously):

- Audio:
 - S/PDIF input and output
 - Three synchronous audio interface (SAI) modules supporting I2S, AC97, TDM, and codec/DSP interfaces
 - MQS interface for medium quality audio via GPIO pads
- Connectivity:
 - One USB 2.0 OTG controller with integrated PHY interface
 - Four universal asynchronous receiver/transmitter (UARTs) modules
 - Two I2C modules
 - Two SPI modules
- GPIO and Pin Multiplexing:
 - General-purpose input/output (GPIO) modules with interrupt capability
 - Input/output multiplexing controller (IOMUXC) to provide centralized pad control
 - 57 GPIOs
 - One FlexIO

The i.MX RT1015 processors integrate advanced power management unit and controllers:

- Full PMIC integration, including on-chip DCDC and LDOs
- Temperature sensor with programmable trip points
- GPC hardware power management controller

The i.MX RT1015 processors support the following system debug:

- Arm CortexM7 CoreSight debug and trace architecture
- Trace Port Interface Unit (TPIU) to support off-chip real-time trace
- Support for 5-pin (JTAG) and SWD debug interfaces selected by eFuse

Security functions are enabled and accelerated by the following hardware:

- High Assurance Boot (HAB)
- Data Co-Processor (DCP):
 - AES-128, ECB, and CBC mode
 - SHA-1 and SHA-256
 - CRC-32

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- Bus Encryption Engine (BEE)
 - AES-128, ECB, and CTR mode
 - On-the-fly QSPI Flash decryption
- True random number generation (TRNG)
- Secure Non-Volatile Storage (SNVS)
 - Secure real-time clock (RTC)
 - Zero Master Key (ZMK)
- Secure JTAG Controller (SJC)

NOTE

The actual feature set depends on the part numbers as described in [Table 1](#). Functions such as display and camera interfaces, connectivity interfaces, and security features are not offered on all derivatives.

1.2 Ordering information

Table 1 provides examples of orderable part numbers covered by this data sheet.

Table 1. Ordering information

| Part Number | Feature | Package | Junction Temperature T _j (°C) |
|-----------------|---|--|--|
| MIMXRT1015CAF4A | Features supports: <ul style="list-style-type: none"> • 396 MHz, industrial grade for general purpose • 128K RAM • USB OTG x1 • SAI x3 • SPDIF x1 • General Purpose Timer x2 • PWM x1 • UART x4 • I²C x2 • SPI x2 • ADC x1 • MQS x1 • FlexIO x1 • QTimer x1 • ENC x1 • DCDC • TRNG x1 • Quad-SPI x1 • WDOG x4 • Security RTC • 57 GPIOs | 14 x 14 mm, 0.5 mm pitch, 100-pin LQFP | -40 to +105 |
| MIMXRT1015CAF4B | Features supports: <ul style="list-style-type: none"> • 396 MHz, industrial grade for general purpose • 128K RAM • USB OTG x1 • SAI x3 • SPDIF x1 • General Purpose Timer x2 • PWM x1 • UART x4 • I²C x2 • SPI x2 • ADC x1 • MQS x1 • FlexIO x1 • QTimer x1 • ENC x1 • DCDC • TRNG x1 • Quad-SPI x1 • WDOG x4 • Security RTC • 57 GPIOs | 14 x 14 mm, 0.5 mm pitch, 100-pin LQFP | -40 to +105 |

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Figure 1 describes the part number nomenclature so that characteristics of a specific part number can be identified (for example, cores, frequency, temperature grade, fuse options, and silicon revision). The primary characteristic which describes which data sheet applies to a specific part is the temperature grade (junction) field.

Ensure to have the proper data sheet for specific part by verifying the temperature grade (junction) field and matching it to the proper data sheet. If there are any questions, visit the web page nxp.com/IMXRT or contact an NXP representative for details.

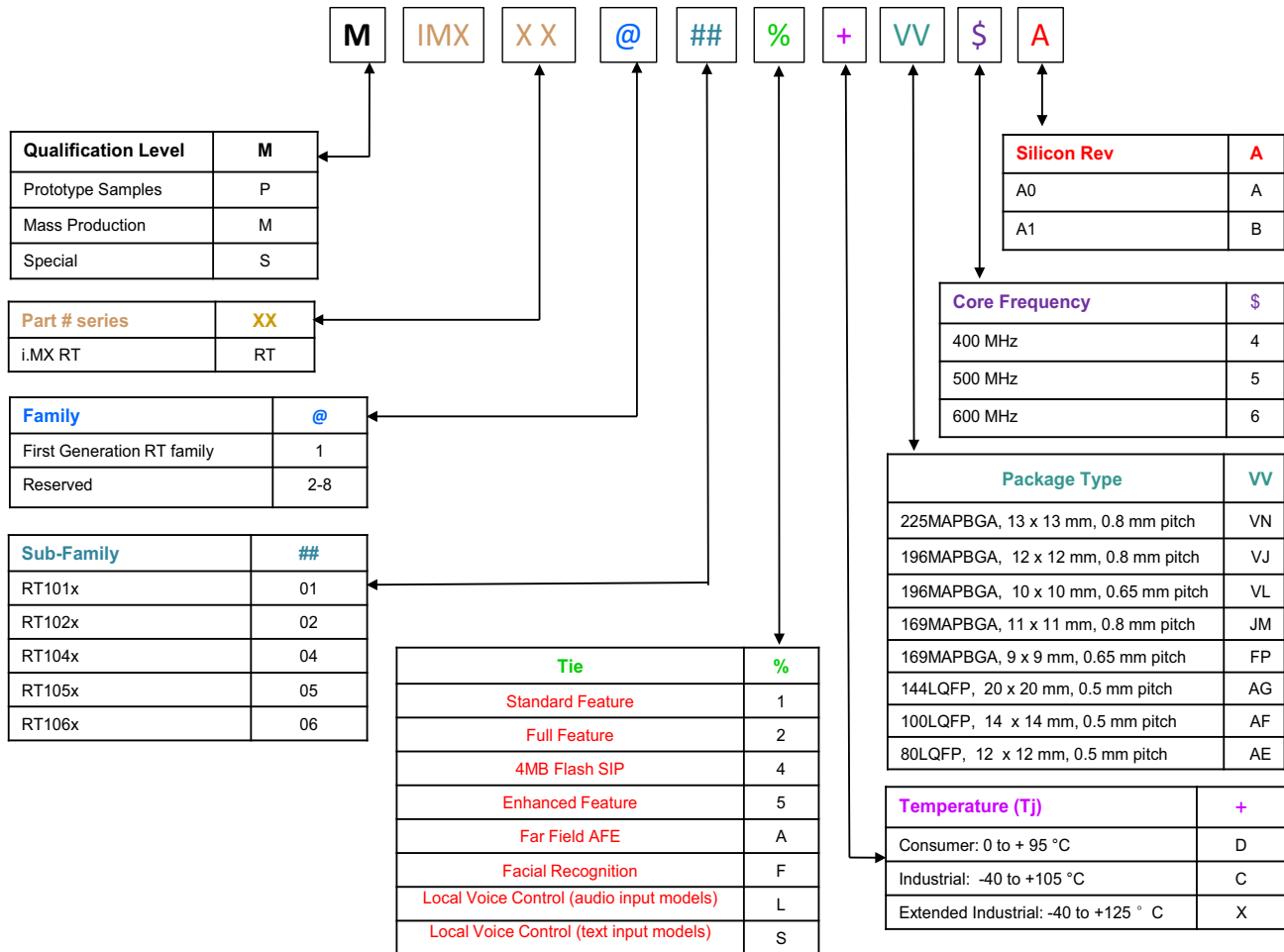


Figure 1. Part number nomenclature—i.MX RT10XX family

2 Architectural overview

The following subsections provide an architectural overview of the i.MX RT1015 processor system.

2.1 Block diagram

Figure 2 shows the functional modules in the i.MX RT1015 processor system¹.

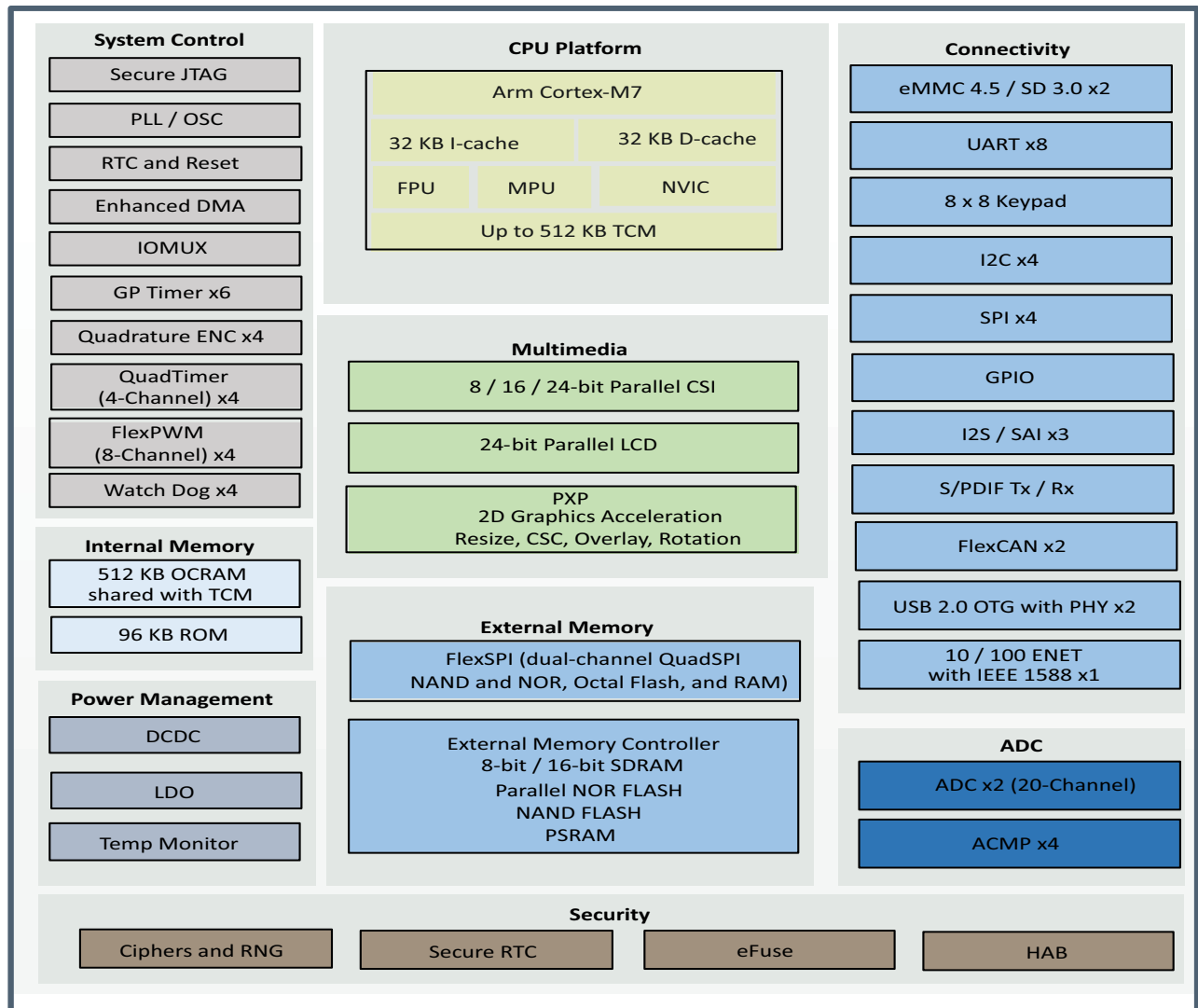


Figure 2. i.MX RT1015 system block diagram

1. Some modules shown in this block diagram are not offered on all derivatives. See Table 1 for details.

3 Modules list

The i.MX RT1015 processors contain a variety of digital and analog modules. [Table 2](#) describes these modules in alphabetical order.

Table 2. i.MX RT1015 modules list

| Block mnemonic | Block name | Subsystem | Brief description |
|-------------------|---|-----------------------------------|--|
| ADC1 | Analog to Digital Converter | Analog | The ADC is a 12-bit general purpose analog to digital converter. |
| AOI | And-Or-Inverter | Cross Trigger | The AOI provides a universal boolean function generator using a four term sum of products expression with each product term containing true or complement values of the four selected inputs (A, B, C, D). |
| Arm | Arm Platform | Arm | The Arm Core Platform includes 1x Cortex-M7 core. It also includes associated sub-blocks, such as Nested Vectored Interrupt Controller (NVIC), Floating-Point Unit (FPU), Memory Protection Unit (MPU), and CoreSight debug modules. |
| BEE | Bus Encryption Engine | Security | On-The-Fly FlexSPI Flash Decryption |
| CCM GPC SRC | Clock Control Module, General Power Controller, System Reset Controller | Clocks, Resets, and Power Control | These modules are responsible for clock and reset distribution in the system, and also for the system power management. |
| CSU | Central Security Unit | Security | The Central Security Unit (CSU) is responsible for setting comprehensive security policy within the i.MX RT1015 platform. |
| DAP | Debug Access Port | System Control Peripherals | The DAP provides real-time access for the debugger without halting the core to: <ul style="list-style-type: none"> • System memory and peripheral registers • All debug configuration registers The DAP also provides debugger access to JTAG scan chains. The DAP module is internal to the Cortex-M7 Core Platform. |
| DCDC | DCDC Converter | Analog | The DCDC module is used for generating power supply for core logic. Main features are: <ul style="list-style-type: none"> • Adjustable high efficiency regulator • Supports 3.3 V input voltage • Supports nominal run and low power standby modes • Supports at 0.9 ~ 1.3 V output in run mode • Supports at 0.9 ~ 1.0 V output in standby mode • Over current and over voltage detection |
| eDMA | enhanced Direct Memory Access | System Control Peripherals | There is an enhanced DMA (eDMA) engine and two DMA_MUX. <ul style="list-style-type: none"> • The eDMA is a 32 channel DMA engine, which is capable of performing complex data transfers with minimal intervention from a host processor. • The DMA_MUX is capable of multiplexing up to 128 DMA request sources to the 32 DMA channels of eDMA. |

Table 2. i.MX RT1015 modules list (continued)

| Block mnemonic | Block name | Subsystem | Brief description |
|----------------------------------|----------------------------------|---------------------------------|---|
| ENC | Quadrature Encoder/Decoder | Timer Peripherals | The enhanced quadrature encoder/decoder module provides interfacing capability to position/speed sensors. There are five input signals: PHASEA, PHASEB, INDEX, TRIGGER, and HOME. This module is used to decode shaft position, revolution count, and speed. |
| EWM | External Watchdog Monitor | Timer Peripherals | The EWM modules is designed to monitor external circuits, as well as the software flow. This provides a back-up mechanism to the internal WDOG that can reset the system. The EWM differs from the internal WDOG in that it does not reset the system. The EWM, if allowed to time-out, provides an independent trigger pin that when asserted resets or places an external circuit into a safe mode. |
| FlexIO1 | Flexible Input/output | Connectivity and Communications | The FlexIO is capable of supporting a wide range of protocols including, but not limited to: UART, I2C, SPI, I2S, camera interface, display interface, PWM waveform generation, etc. The module can remain functional when the chip is in a low power mode provided the clock it is using remain active. |
| FlexPWM1 | Pulse Width Modulation | Timer Peripherals | The pulse-width modulator (PWM) contains four PWM sub-modules, each of which is set up to control a single half-bridge power stage. Fault channel support is provided. The PWM module can generate various switching patterns, including highly sophisticated waveforms. |
| FlexRAM | RAM | Memories | The i.MX RT1015 has 128 KB of on-chip RAM which could be flexible allocated to I-TCM, D-TCM, and on-chip RAM (OCRAM) in a 32 KB granularity. The FlexRAM is the manager of the 128 KB on-chip RAM array. Major functions of this blocks are: interfacing to I-TCM and D-TCM of Arm core and OCRAM controller; dynamic RAM arrays allocation for I-TCM, D-TCM, and OCRAM. |
| FlexSPI | Quad Serial Peripheral Interface | Connectivity and Communications | FlexSPI acts as an interface to one or two external serial flash devices, each with up to four bidirectional data lines. |
| GPIO1 GPIO2 GPIO3 GPIO5 | General Purpose I/O Modules | System Control Peripherals | Used for general purpose input/output to external ICs. Each GPIO module supports up to 32 bits of I/O. |

Table 2. i.MX RT1015 modules list (continued)

| Block mnemonic | Block name | Subsystem | Brief description |
|--|---------------------------------------|---------------------------------|---|
| GPT1 GPT2 | General Purpose Timer | Timer Peripherals | Each GPT is a 32-bit “free-running” or “set and forget” mode timer with programmable prescaler and compare and capture register. A timer counter value can be captured using an external event and can be configured to trigger a capture event on either the leading or trailing edges of an input pulse. When the timer is configured to operate in “set and forget” mode, it is capable of providing precise interrupts at regular intervals with minimal processor intervention. The counter has output compare logic to provide the status and interrupt at comparison. This timer can be configured to run either on an external clock or on an internal clock. |
| KPP | Keypad Port | Human Machine Interfaces | The KPP is a 16-bit peripheral that can be used as a keypad matrix interface or as general purpose input/output (I/O). It supports 4 x 4 external key pad matrix. Main features are: <ul style="list-style-type: none"> • Multiple-key detection • Long key-press detection • Standby key-press detection • Supports a 2-point and 3-point contact key matrix |
| LPI2C1 LPI2C2 | Low Power Inter-integrated Circuit | Connectivity and Communications | The LPI2C is a low power Inter-Integrated Circuit (I2C) module that supports an efficient interface to an I2C bus as a master. The I2C provides a method of communication between a number of external devices. More detailed information, see Section 4.8.2, LPI2C module timing parameters . |
| LPSP1 LPSP2 | Low Power Serial Peripheral Interface | Connectivity and Communications | The LPSP1 is a low power Serial Peripheral Interface (SPI) module that support an efficient interface to an SPI bus as a master and/or a slave. <ul style="list-style-type: none"> • It can continue operating while the chip is in stop modes, if an appropriate clock is available • Designed for low CPU overhead, with DMA off loading of FIFO register access |
| LPUART1 LPUART2 LPUART3 LPUART4 | UART Interface | Connectivity Peripherals | Each of the UART modules support the following serial data transmit/receive protocols and configurations: <ul style="list-style-type: none"> • 7- or 8-bit data words, 1 or 2 stop bits, programmable parity (even, odd or none) • Programmable baud rates up to 20 Mbps. |
| MQS | Medium Quality Sound | Multimedia Peripherals | MQS is used to generate 2-channel medium quality PWM-like audio via two standard digital GPIO pins. |

Table 2. i.MX RT1015 modules list (continued)

| Block mnemonic | Block name | Subsystem | Brief description |
|----------------------|---|---------------------------------|--|
| QuadTimer1 | QuadTimer | Timer Peripherals | The quad-timer provides four timer channels with a variety of controls affecting both individual and multi-channel features. Specific features include up/down count, cascading of counters, programmable module, count once/repeated, counter preload, compare registers with preload, shared use of input signals, prescaler controls, independent capture/compare, fault input control, programmable input filters, and multi-channel synchronization. |
| ROMCP | ROM Controller with Patch | Memories and Memory Controllers | The ROMCP acts as an interface between the Arm advanced high-performance bus and the ROM. The on-chip ROM is only used by the Cortex-M7 core during boot up. Size of the ROM is 96 KB. |
| RTC OSC | Real Time Clock Oscillator | Clock Sources and Control | The RTC OSC provides the clock source for the Real-Time Clock module. The RTC OSC module, in conjunction with an external crystal, generates a 32.768 kHz reference clock for the RTC. |
| RTWDOG | Watch Dog | Timer Peripherals | The RTWDG module is a high reliability independent timer that is available for system to use. It provides a safety feature to ensure software is executing as planned and the CPU is not stuck in an infinite loop or executing unintended code. If the WDOG module is not serviced (refreshed) within a certain period, it resets the MCU. Windowed refresh mode is supported as well. |
| SAI1 SAI2 SAI3 | Synchronous Audio Interface | Multimedia Peripherals | The SAI module provides a synchronous audio interface (SAI) that supports full duplex serial interfaces with frame synchronization, such as I2S, AC97, TDM, and codec/DSP interfaces. |
| SA-TRNG | Standalone True Random Number Generator | Security | The SA-TRNG is hardware accelerator that generates a 512-bit entropy as needed by an entropy consuming module or by other post processing functions. |
| SJC | System JTAG Controller | System Control Peripherals | The SJC provides JTAG interface, which complies with JTAG TAP standards, to internal logic. The i.MX RT1015 processors use JTAG port for production, testing, and system debugging. In addition, the SJC provides BSR (Boundary Scan Register) standard support, which complies with IEEE1149.1 and IEEE1149.6 standards. The JTAG port is accessible during platform initial laboratory bring-up, for manufacturing tests and troubleshooting, as well as for software debugging by authorized entities. The i.MX RT1015 SJC incorporates three security modes for protecting against unauthorized accesses. Modes are selected through eFUSE configuration. |
| SNVS | Secure Non-Volatile Storage | Security | Secure Non-Volatile Storage, including Secure Real Time Clock, Security State Machine, and Master Key Control. |

Table 2. i.MX RT1015 modules list (continued)

| Block mnemonic | Block name | Subsystem | Brief description |
|----------------|--|--------------------------|--|
| SPDIF | Sony Philips Digital Interconnect Format | Multimedia Peripherals | A standard audio file transfer format, developed jointly by the Sony and Phillips corporations. Has Transmitter and Receiver functionality. |
| Temp Monitor | Temperature Monitor | Analog | The temperature sensor implements a temperature sensor/conversion function based on a temperature-dependent voltage to time conversion. |
| USBO2 | Universal Serial Bus 2.0 | Connectivity Peripherals | USBO2 (USB OTG1) contains: <ul style="list-style-type: none"> • One high-speed OTG 2.0 module with integrated HS USB PHYs • Support eight Transmit (TX) and eight Receive (Rx) endpoints, including endpoint 0 |
| WDOG1 WDOG2 | Watch Dog | Timer Peripherals | The Watch Dog Timer supports two comparison points during each counting period. Each of the comparison points is configurable to evoke an interrupt to the Arm core, and a second point evokes an external event on the WDOG line. |
| XBAR | Cross BAR | Cross Trigger | Each crossbar switch is an array of muxes with shared inputs. Each mux output provides one output of the crossbar. The number of inputs and the number of muxes/outputs are user configurable and registers are provided to select which of the shared inputs are routed to each output. |

3.1 Special signal considerations

Table 3 lists special signal considerations for the i.MX RT1015 processors. The signal names are listed in alphabetical order.

The package contact assignments can be found in [Section 6, Package information and contact assignments](#). Signal descriptions are provided in the *i.MX RT1015 Reference Manual (IMXRT1015RM)*.

Table 3. Special signal considerations

| Signal name | Remarks |
|---------------------|---|
| DCDC_PSWITCH | PAD is in DCDC_IN domain and connected the ground to bypass DCDC. To enable DCDC function, assert to DCDC_IN with at least 1ms delay for DCDC_IN rising edge. |
| RTC_XTALI/RTC_XTALO | If the user wishes to configure RTC_XTALI and RTC_XTALO as an RTC oscillator, a 32.768 kHz crystal, (≤ 100 k Ω ESR, 10 pF load) should be connected between RTC_XTALI and RTC_XTALO. Keep in mind the capacitors implemented on either side of the crystal are about twice the crystal load capacitor. To hit the exact oscillation frequency, the board capacitors need to be reduced to account for board and chip parasitics. The integrated oscillation amplifier is self biasing, but relatively weak. Care must be taken to limit parasitic leakage from RTC_XTALI and RTC_XTALO to either power or ground (>100 M Ω). This will debias the amplifier and cause a reduction of startup margin. Typically RTC_XTALI and RTC_XTALO should bias to approximately 0.5 V. If it is desired to feed an external low frequency clock into RTC_XTALI the RTC_XTALO pin must remain unconnected or driven with a complimentary signal. The logic level of this forcing clock should not exceed VDD_SNVS_CAP level and the frequency should be <100 kHz under typical conditions. In case when high accuracy real time clock are not required system may use internal low frequency ring oscillator. It is recommended to connect RTC_XTALI to GND and keep RTC_XTALO unconnected. |
| XTALI/XTALO | A 24.0 MHz crystal should be connected between XTALI and XTALO. External load capacitance value depends on the typical load capacitance of crystal used and PCB design. The crystal must be rated for a maximum drive level of 250 μ W. An ESR (equivalent series resistance) of typical 80 Ω is recommended. NXP SDK software requires 24 MHz on XTALI/XTALO. The crystal can be eliminated if an external 24 MHz oscillator is available in the system. In this case, XTALO must be directly driven by the external oscillator and XTALI mounted with 18 pF capacitor. The logic level of this forcing clock cannot exceed NVCC_PLL level. If this clock is used as a reference for USB, then there are strict frequency tolerance and jitter requirements. See OSC24M chapter and relevant interface specifications chapters for details. |
| GPANAIO | This signal is reserved for NXP manufacturing use only. This output must remain unconnected. |
| JTAG_##### | The JTAG interface is summarized in Table 4 . Use of external resistors is unnecessary. However, if external resistors are used, the user must ensure that the on-chip pull-up/down configuration is followed. For example, do not use an external pull down on an input that has on-chip pull-up. JTAG_TDO is configured with a keeper circuit such that the non-connected condition is eliminated if an external pull resistor is not present. An external pull resistor on JTAG_TDO is detrimental and should be avoided. JTAG_MOD is referenced as SJC_MOD in the i.MX RT1015 reference manual. Both names refer to the same signal. JTAG_MOD must be externally connected to GND for normal operation. Termination to GND through an external pull-down resistor (such as 1 k Ω) is allowed. JTAG_MOD set to hi configures the JTAG interface to mode compliant with IEEE1149.1 standard. JTAG_MOD set to low configures the JTAG interface for common SW debug adding all the system TAPs to the chain. |
| NC | These signals are No Connect (NC) and should be disconnected by the user. |

Table 3. Special signal considerations (continued)

| Signal name | Remarks |
|-------------|--|
| POR_B | This cold reset negative logic input resets all modules and logic in the IC. May be used in addition to internally generated power on reset signal (logical AND, both internal and external signals are considered active low). |
| ONOFF | ONOFF can be configured in debounce, off to on time, and max time-out configurations. The debounce and off to on time configurations supports 0, 50, 100 and 500 ms. Debounce is used to generate the power off interrupt. While in the ON state, if ONOFF button is pressed longer than the debounce time, the power off interrupt is generated. Off to on time supports the time it takes to request power on after a configured button press time has been reached. While in the OFF state, if ONOFF button is pressed longer than the off to on time, the state will transition from OFF to ON. Max time-out configuration supports 5, 10, 15 seconds and disable. Max time-out configuration supports the time it takes to request power down after ONOFF button has been pressed for the defined time. |
| TEST_MODE | TEST_MODE is for NXP factory use. The user can leave this signal floating or tie it to ground. |
| WAKEUP | A GPIO powered by SNVS domain power supply which can be configured as wakeup source in SNVS mode. |

Table 4. JTAG controller interface summary

| JTAG | I/O type | On-chip termination |
|------------|----------------|---------------------|
| JTAG_TCK | Input | 100 kΩ pull-down |
| JTAG_TMS | Input | 47 kΩ pull-up |
| JTAG_TDI | Input | 47 kΩ pull-up |
| JTAG_TDO | 3-state output | Keeper |
| JTAG_TRSTB | Input | 47 kΩ pull-up |
| JTAG_MOD | Input | 100 kΩ pull-down |

3.2 Recommended connections for unused analog interfaces

Table 5 shows the recommended connections for unused analog interfaces.

Table 5. Recommended connections for unused analog interfaces

| Module | Pad name | Recommendations if unused |
|--------|---|---|
| USB | USB_OTG1_CHD_B, USB_OTG1_DN, USB_OTG1_DP, USB_OTG1_VBUS | Not connected |
| ADC | VDDA_ADC_3P3 | VDDA_ADC_3P3 must be powered even if the ADC is not used. |

4 Electrical characteristics

This section provides the device and module-level electrical characteristics for the i.MX RT1015 processors.

4.1 Chip-level conditions

This section provides the device-level electrical characteristics for the IC. See [Table 6](#) for a quick reference to the individual tables and sections.

Table 6. i.MX RT1015 chip-Level conditions

| For these characteristics | Topic appears |
|--|----------------------------|
| Absolute maximum ratings | on page 15 |
| Thermal resistance | on page 16 |
| Operating ranges | on page 17 |
| External clock sources | on page 18 |
| Maximum supply currents | on page 19 |
| Low power mode supply currents | on page 20 |
| USB PHY current consumption | on page 20 |

4.1.1 Absolute maximum ratings

CAUTION

Stress beyond those listed under [Table 7](#) may cause permanent damage to the device. These are stress ratings only. Functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

[Table 7](#) shows the absolute maximum operating ratings.

Table 7. Absolute maximum ratings

| Parameter Description | Symbol | Min | Max | Unit |
|---|---------------|------|-----|------|
| Core supplies input voltage | VDD_SOC_IN | -0.3 | 1.6 | V |
| VDD_HIGH_IN supply voltage | VDD_HIGH_IN | -0.3 | 3.7 | V |
| Power for DCDC | DCDC_IN | -0.3 | 3.6 | V |
| Supply input voltage to Secure Non-Volatile Storage and Real Time Clock | VDD_SNVS_IN | -0.3 | 3.6 | V |
| USB VBUS supply | USB_OTG1_VBUS | — | 5.5 | V |
| Supply for 12-bit ADC | VDDA_ADC | 3 | 3.6 | V |
| IO supply for GPIO bank (3.3 V mode) | NVCC_GPIO | 3 | 3.6 | V |

Electrical characteristics

Table 7. Absolute maximum ratings (continued)

| | | | | |
|----------------------------|----------------------|------|-------------------------|----|
| ESD Damage Immunity: | Vesd | | | |
| Human Body Model (HBM) | | — | 1000 | V |
| Charge Device Model (CDM) | | — | 500 | |
| Input/Output Voltage range | V _{in/Vout} | -0.5 | OVDD + 0.3 ¹ | V |
| Storage Temperature range | T _{STORAGE} | -40 | 150 | °C |

¹ OVDD is the I/O supply voltage.

4.1.2 Thermal resistance

Following sections provide the thermal resistance data.

4.1.2.1 14 x 14 mm package thermal resistance

Table 8 displays the 14 x 14 mm LQFP package thermal resistance data.

Table 8. 14 x 14 mm package thermal resistance data

| Rating | Test Conditions | Symbol | Value | Unit | Notes |
|---|-------------------------|-------------------|-------|------|-------|
| Junction to Ambient Natural convection | Single-layer board (1s) | R _{θJA} | 63 | °C/W | 1,2 |
| Junction to Ambient Natural convection | Four-layer board (2s2p) | R _{θJA} | 52 | °C/W | 1,2 |
| Junction to Ambient (@200 ft/min) | Single layer board (1s) | R _{θJMA} | 53 | °C/W | 1,3 |
| Junction to Ambient (@200 ft/min) | Four layer board (2s2p) | R _{θJMA} | 46 | °C/W | 1,3 |
| Junction to Board | — | R _{θJB} | 36 | °C/W | 4 |
| Junction to Case | — | R _{θJC} | 19 | °C/W | 5 |
| Junction to Package Top | Natural Convection | Ψ _{JT} | 3 | °C/W | 6 |

¹ Junction temperature is a function of die size, on-chip power dissipation, package thermal resistance, mounting site (board) temperature, ambient temperature, air flow, power dissipation of other components on the board, and board thermal resistance.

² Per JEDEC JESD51-2 with natural convection for horizontally oriented board. Board meets JESD51-9 specification for 1s or 2s2p board, respectively.

³ Per JEDEC JESD51-6 with forced convection for horizontally oriented board. Board meets JESD51-9 specification for 1s or 2s2p board, respectively.

⁴ Thermal resistance between the die and the printed circuit board per JEDEC JESD51-8. Board temperature is measured on the top surface of the board near the package.

⁵ Thermal resistance between the die and the case top surface as measured by the cold plate method (MIL SPEC-883 Method 1012.1).

⁶ Thermal characterization parameter indicating the temperature difference between package top and the junction temperature per JEDEC JESD51-2. When Greek letters are not available, the thermal characterization parameter is written as Psi-JT.

4.1.3 Operating ranges

Table 9 provides the operating ranges of the i.MX RT1015 processors. For details on the chip's power structure, see the “Power Management Unit (PMU)” chapter of the *i.MX RT1015 Reference Manual (IMXRT1015RM)*.

Table 9. Operating ranges

| Parameter Description | Symbol | Operating Conditions | Min | Typ | Max ¹ | Unit | Comment |
|------------------------------------|------------------------------------|---------------------------------------|-------------|-----|------------------|------|---|
| Run Mode | VDD_SOC_IN | M7 core at 396 MHz | 1.15 | — | 1.26 | V | — — |
| | VDD_SOC_IN | M7 core at 132 MHz | 1.15 | — | 1.26 | | |
| | | M7 core at 24 MHz | 0.925 | — | 1.26 | | |
| IDLE Mode | VDD_SOC_IN | M7 core operation at 396 MHz or below | 1.15 | — | 1.26 | V | — |
| SUSPEND (DSM) Mode | VDD_SOC_IN | — | 0.925 | — | 1.26 | V | Refer to Table 12 Low power mode current and power consumption |
| SNVS Mode | VDD_SOC_IN | — | 0 | — | 1.26 | V | — |
| Power for DCDC | DCDC_IN | — | 3.0 | 3.3 | 3.6 | — | — |
| VDD_HIGH internal regulator | VDD_HIGH_IN ² | — | 3.0 | — | 3.6 | V | Must match the range of voltages that the rechargeable backup battery supports. |
| Backup battery supply range | VDD_SNVS_IN ³ | — | 2.40 | — | 3.6 | V | Can be combined with VDDHIGH_IN, if the system does not require keeping real time and other data on OFF state. |
| USB supply voltages | USB_OTG1_VBUS | — | 4.40 | — | 5.5 | V | — |
| GPIO supplies | NVCC_GPIO | — | 3.0 | 3.3 | 3.6 | V | All digital I/O supplies (NVCC_xxxx) must be powered (unless otherwise specified in this data sheet) under normal conditions whether the associated I/O pins are in use or not. |
| A/D converter | VDDA_ADC_3P3 | — | 3.0 | 3.3 | 3.6 | V | VDDA_ADC_3P3 must be powered even if the ADC is not used. VDDA_ADC_3P3 cannot be powered when the other SoC supplies (except VDD_SNVS_IN) are off. |
| System frequency/ Bus frequency | F _{SYS} /F _{BUS} | — | 396/ 132 | —/— | 24/ 24 | MHz | — |

Table 9. Operating ranges (continued)

| Temperature Operating Ranges | | | | | | | |
|------------------------------|----------------|------------|-----|---|-----|----|---|
| Junction temperature | T _j | Industrial | -40 | — | 105 | °C | See the application note, i.MX RT1015 Product Lifetime Usage Estimates for information on product lifetime (power-on years) for this processor. |

¹ Applying the maximum voltage results in maximum power consumption and heat generation. NXP recommends a voltage set point = (V_{\min} + the supply tolerance). This result in an optimized power/speed ratio.

² Applying the maximum voltage results in shorten lifetime. 3.6 V usage limited to < 1% of the use profile. Reset of profile limited to below 3.49 V.

³ In setting VDD_SNVS_IN voltage with regards to Charging Currents and RTC, refer to the *i.MX RT1015 Hardware Development Guide* (IMXRT1015HDG).

4.1.4 External clock sources

Each i.MX RT1015 processor has two external input system clocks: a low frequency (RTC_XTALI) and a high frequency (XTALI).

The RTC_XTALI is used for low-frequency functions. It supplies the clock for wake-up circuit, power-down real time clock operation, and slow system and watch-dog counters. The clock input can be connected to either external oscillator or a crystal using internal oscillator amplifier. Additionally, there is an internal ring oscillator, which can be used instead of the RTC_XTALI if accuracy is not important.

The system clock input XTALI is used to generate the main system clock. It supplies the PLLs and other peripherals. The system clock input can be connected to either external oscillator or a crystal using internal oscillator amplifier.

Table 10 shows the interface frequency requirements.

Table 10. External input clock frequency

| Parameter Description | Symbol | Min | Typ | Max | Unit |
|-------------------------------------|-------------------|-----|---------------------------|-----|------|
| RTC_XTALI Oscillator ^{1,2} | f _{ckil} | — | 32.768 ³ /32.0 | — | kHz |
| XTALI Oscillator ^{2,4} | f _{xtal} | — | 24 | — | MHz |

¹ External oscillator or a crystal with internal oscillator amplifier.

² The required frequency stability of this clock source is application dependent. For recommendations, see the *Hardware Development Guide for i.MX RT1015 Crossover Processors* (IMXRT1015HDG).

³ Recommended nominal frequency 32.768 kHz.

⁴ External oscillator or a fundamental frequency crystal with internal oscillator amplifier.

The typical values shown in Table 10 are required for use with NXP SDK to ensure precise time keeping and USB operation. For RTC_XTALI operation, two clock sources are available.

- On-chip 40 kHz ring oscillator—this clock source has the following characteristics:
 - Approximately 25 μ A more I_{dd} than crystal oscillator
 - Approximately \pm 50% tolerance
 - No external component required

- Starts up quicker than 32 kHz crystal oscillator
- External crystal oscillator with on-chip support circuit:
 - At power up, ring oscillator is utilized. After crystal oscillator is stable, the clock circuit switches over to the crystal oscillator automatically.
 - Higher accuracy than ring oscillator
 - If no external crystal is present, then the ring oscillator is utilized

The decision of choosing a clock source should be taken based on real-time clock use and precision time-out.

4.1.5 Maximum supply currents

The data shown in [Table 11](#) represent a use case designed specifically to show the maximum current consumption possible. All cores are running at the defined maximum frequency and are limited to L1 cache accesses only to ensure no pipeline stalls. Although a valid condition, it would have a very limited practical use case, if at all, and be limited to an extremely low duty cycle unless the intention was to specifically show the worst case power consumption.

See the *i.MX RT1015 Power Consumption Measurement Application Note* for more details on typical power consumption under various use case definitions.

Table 11. Maximum supply currents

| Power Rail | Conditions | Max Current | Unit |
|---------------|---|-------------|------|
| DCDC_IN | Max power for chip at 105 °C with core mark run on FlexRAM | 90 | mA |
| VDD_HIGH_IN | Include internal loading in analog | 50 | mA |
| VDD_SNVS_IN | — | 250 | μA |
| USB_OTG1_VBUS | 25 mA for each active USB interface | 25 | mA |
| VDDA_ADC_3P3 | 3.3 V power supply for 12-bit ADC, 600 μA typical, 750 μA max, for each ADC. 100 Ohm max loading for touch panel, cause 33 mA current. | 40 | mA |
| NVCC_GPIO | $I_{max} = N \times C \times V \times (0.5 \times F)$ Where: N—Number of IO pins supplied by the power line C—Equivalent external capacitive load V—IO voltage (0.5 x F)—Data change rate. Up to 0.5 of the clock rate (F). In this equation, I _{max} is in Amps, C in Farads, V in Volts, and F in Hertz. | | |

4.1.6 Low power mode supply currents

Table 12 shows the current core consumption (not including I/O) of i.MX RT1015 processors in selected low power modes.

Table 12. Low power mode current and power consumption

| Mode | Test Conditions | Supply | Typical ¹ | Units |
|----------------|--|---------------------|----------------------|-------|
| SYSTEM IDLE | <ul style="list-style-type: none"> LDO_ARM and LDO_SOC set to the Bypass mode LDO_2P5 set to 2.5 V, LDO_1P1 set to 1.1 V CPU in WFI, CPU clock gated 24 MHz XTAL is ON System PLL is active, other PLLs are power down Peripheral clock gated, but remain powered | DCDC_IN (3.3 V) | 3.82 | mA |
| | | VDD_HIGH_IN (3.3 V) | 5.93 | |
| | | VDD_SNVS_IN (3.3 V) | 0.025 | |
| | | Total | 32.258 | mW |
| LOW POWER IDLE | <ul style="list-style-type: none"> LDO_SOC is in the Bypass mode, LDO_ARM is in the PG mode LDO_2P5 and LDO_1P1 are set to Weak mode CPU in Power Gate mode All PLLs are power down 24 MHz XTAL is off, 24 MHz RCOSC used as clock source Peripheral are powered off | DCDC_IN (3.3 V) | 1.13 | mA |
| | | VDD_HIGH_IN (3.3 V) | 0.287 | |
| | | VDD_SNVS_IN (3.3 V) | 0.046 | |
| | | Total | 4.828 | mW |
| SUSPEND (DSM) | <ul style="list-style-type: none"> LDO_SOC is in the Bypass mode, LDO_ARM is in the PG mode LDO_2P5 and LDO_1P1 are shut off CPU in Power Gate mode All PLLs are power down 24 MHz XTAL is off, 24 MHz RCOSC is off All clocks are shut off, except 32 kHz RTC Peripheral are powered off | DCDC_IN (3.3 V) | 0.19 | mA |
| | | VDD_HIGH_IN (3.3 V) | 0.09 | |
| | | VDD_SNVS_IN (3.3 V) | 0.018 | |
| | | Total | 1.019 | mW |
| SNVS (RTC) | <ul style="list-style-type: none"> All SOC digital logic, analog module are shut off 32 kHz RTC is alive | DCDC_IN (0 V) | 0 | mA |
| | | VDD_HIGH_IN (0 V) | 0 | |
| | | VDD_SNVS_IN (3.3 V) | 0.018 | |
| | | Total | 0.059 | mW |

¹ The typical values shown here are for information only and are not guaranteed. These values are average values measured on a typical process wafer at 25°C.

4.1.7 USB PHY current consumption

4.1.7.1 Power down mode

In power down mode, everything is powered down, including the USB VBUS valid detectors in typical condition. Table 13 shows the USB interface current consumption in power down mode.

Table 13. USB PHY current consumption in power down mode

| | VDD_USB_CAP (3.0 V) | VDD_HIGH_CAP (2.5 V) | NVCC_PLL (1.1 V) |
|---------|---------------------|----------------------|------------------|
| Current | 5.1 μ A | 1.7 μ A | < 0.5 μ A |

NOTE

The currents on the VDD_HIGH_CAP and VDD_USB_CAP were identified to be the voltage divider circuits in the USB-specific level shifters.

4.2 System power and clocks

This section provide the information about the system power and clocks.

4.2.1 Power supplies requirements and restrictions

The system design must comply with power-up sequence, power-down sequence, and steady state guidelines as described in this section to guarantee the reliable operation of the device. Any deviation from these sequences may result in the following situations:

- Excessive current during power-up phase
- Prevention of the device from booting
- Irreversible damage to the processor (worst-case scenario)

4.2.1.1 Power-up sequence

The below restrictions must be followed:

- VDD_SNVS_IN supply must be turned on before any other power supply or be connected (shorted) with VDD_HIGH_IN supply.
- If a coin cell is used to power VDD_SNVS_IN, then ensure that it is connected before any other supply is switched on.
- When internal DCDC is enabled, external delay circuit is required to delay the “DCDC_PSWITCH” signal 1 ms after DCDC_IN is stable.
- Need to ensure DCDC_IN ramps to 3.0 V within $0.2 \times RC$, RC is from external delay circuit used for DCDC_PSWITCH and RC must be longer than 1 ms.
- POR_B should be held low during the entire power up sequence.

NOTE

The POR_B input (if used) must be immediately asserted at power-up and remain asserted until after the last power rail reaches its working voltage. In the absence of an external reset feeding the POR_B input, the internal POR module takes control. See the *i.MX RT1015 Reference Manual (IMXRT1015RM)* for further details and to ensure that all necessary requirements are being met.

NOTE

Need to ensure that there is no back voltage (leakage) from any supply on the board towards the 3.3 V supply (for example, from the external components that use both the 1.8 V and 3.3 V supplies).

NOTE

USB_OTG1_VBUS and VDDA_ADC_3P3 are not part of the power supply sequence and may be powered at any time.

4.2.1.2 Power-down sequence

The following restrictions must be followed:

- VDD_SNVS_IN supply must be turned off after any other power supply or be connected (shorted) with VDD_HIGH_IN supply.
- If a coin cell is used to power VDD_SNVS_IN, then ensure that it is removed after any other supply is switched off.

4.2.1.3 Power supplies usage

All I/O pins should not be externally driven while the I/O power supply for the pin (NVCC_XXX) is OFF. This can cause internal latch-up and malfunctions due to reverse current flows. For information about I/O power supply of each pin, see “Power Rail” columns in pin list tables of [Section 6, Package information and contact assignments](#).”

4.2.2 Integrated LDO voltage regulator parameters

Various internal supplies can be powered ON from internal LDO voltage regulators. All the supply pins named *_CAP must be connected to external capacitors. The on-board LDOs are intended for internal use only and should not be used to power any external circuitry. See the *i.MX RT1015 Reference Manual (IMXRT1015RM)* for details on the power tree scheme.

NOTE

The *_CAP signals should not be powered externally. These signals are intended for internal LDO operation only.

4.2.2.1 Digital regulators (LDO_SNVS)

There are one digital LDO regulator (“Digital”, because of the logic loads that they drive, not because of their construction). The advantages of the regulator is to reduce the input supply variation because of its input supply ripple rejection and its on-die trimming. This translates into more stable voltage for the on-chip logics.

The regulator has two basic modes:

- Power Gate. The regulation FET is switched fully off limiting the current draw from the supply. The analog part of the regulator is powered down here limiting the power consumption.
- Analog regulation mode. The regulation FET is controlled such that the output voltage of the regulator equals the programmed target voltage. The target voltage is fully programmable in 25 mV steps.

For additional information, see the *i.MX RT1015 Reference Manual (IMXRT1015RM)*.

4.2.2.2 Regulators for analog modules

4.2.2.2.1 LDO_1P1

The LDO_1P1 regulator implements a programmable linear-regulator function from VDD_HIGH_IN (see [Table 9](#) for minimum and maximum input requirements). Typical Programming Operating Range is 1.0 V to 1.2 V with the nominal default setting as 1.1 V. The LDO_1P1 supplies the USB Phy, and PLLs. A programmable brown-out detector is included in the regulator that can be used by the system to determine when the load capability of the regulator is being exceeded to take the necessary steps. Current-limiting can be enabled to allow for in-rush current requirements during start-up, if needed. Active-pull-down can also be enabled for systems requiring this feature.

For information on external capacitor requirements for this regulator, see the *Hardware Development Guide for i.MX RT1015 Crossover Processors* (IMXRT1015HDG).

For additional information, see the *i.MX RT1015 Reference Manual* ([IMXRT1015RM](#)).

4.2.2.2.2 LDO_2P5

The LDO_2P5 module implements a programmable linear-regulator function from VDD_HIGH_IN (see [Table 9](#) for minimum and maximum input requirements). Typical Programming Operating Range is 2.25 V to 2.75 V with the nominal default setting as 2.5 V. LDO_2P5 supplies the USB PHY, E-fuse module, and PLLs. A programmable brown-out detector is included in the regulator that can be used by the system to determine when the load capability of the regulator is being exceeded, to take the necessary steps. Current-limiting can be enabled to allow for in-rush current requirements during start-up, if needed. Active-pull-down can also be enabled for systems requiring this feature. An alternate self-biased low-precision weak-regulator is included that can be enabled for applications needing to keep the output voltage alive during low-power modes where the main regulator driver and its associated global bandgap reference module are disabled. The output of the weak-regulator is not programmable and is a function of the input supply as well as the load current. Typically, with a 3 V input supply the weak-regulator output is 2.525 V and its output impedance is approximately 40 Ω .

For information on external capacitor requirements for this regulator, see the *Hardware Development Guide for i.MX RT1015 Crossover Processors* (IMXRT1015HDG).

For additional information, see the *i.MX RT1015 Reference Manual* ([IMXRT1015RM](#)).

4.2.2.2.3 LDO_USB

The LDO_USB module implements a programmable linear-regulator function from the USB VUSB voltages (4.4 V–5.5 V) to produce a nominal 3.0 V output voltage. A programmable brown-out detector is included in the regulator that can be used by the system to determine when the load capability of the regulator is being exceeded, to take the necessary steps. This regulator has a built in power-mux that allows the user to select to run the regulator from USB VBUS supply. Current limit is also included to help the system meet in-rush current targets.

For information on external capacitor requirements for this regulator, see the *Hardware Development Guide for i.MX RT1015 Crossover Processors* (IMXRT1015HDG).

Electrical characteristics

For additional information, see the *i.MX RT1015 Reference Manual* ([IMXRT1015RM](#)).

4.2.2.2.4 DCDC

DCDC can be configured to operate on power-save mode when the load current is less than 50 mA. During the power-save mode, the converter operates with reduced switching frequency in PFM mode and with a minimum quiescent current to maintain high efficiency.

DCDC can detect the peak current in the P-channel switch. When the peak current exceeds the threshold, DCDC will give an alert signal, and the threshold can be configured. By this way, DCDC can roughly detect the current loading.

DCDC also includes the following protection functions:

- Over current protection. In run mode, DCDC shuts down when detecting abnormal large current in the P-type power switch. In power save mode, DCDC stop charging inductor when detecting large current in the P-type power switch. The threshold is also different in run mode and in power save mode: the former is 1 A–2A, and the latter is 200 mA–250 mA.
- Over voltage protection. DCDC shuts down when detecting the output voltage is too high.
- Low voltage detection. DCDC shuts down when detecting the input voltage is too low.

For additional information, see the *i.MX RT1015 Reference Manual* ([IMXRT1015RM](#)).

4.2.3 PLL's electrical characteristics

This section provides PLL electrical characteristics.

4.2.3.1 Audio/Video PLL's electrical parameters

Table 14. Audio/video PLL's electrical parameters

| Parameter | Value |
|--------------------|--------------------------|
| Clock output range | 650 MHz–1.3 GHz |
| Reference clock | 24 MHz |
| Lock time | < 11250 reference cycles |

4.2.3.2 System PLL

Table 15. System PLL's electrical parameters

| Parameter | Value |
|--------------------|--------------------------|
| Clock output range | 528 MHz PLL output |
| Reference clock | 24 MHz |
| Lock time | < 11250 reference cycles |

4.2.3.3 Ethernet PLL

Table 16. Ethernet PLL's electrical parameters

| Parameter | Value |
|--------------------|--------------------------|
| Clock output range | 1 GHz |
| Reference clock | 24 MHz |
| Lock time | < 11250 reference cycles |

4.2.3.4 USB PLL

Table 17. USB PLL's electrical parameters

| Parameter | Value |
|--------------------|------------------------|
| Clock output range | 480 MHz PLL output |
| Reference clock | 24 MHz |
| Lock time | < 383 reference cycles |

4.2.4 On-chip oscillators

4.2.4.1 OSC24M

This block implements an amplifier that when combined with a suitable quartz crystal and external load capacitors implement an oscillator. The oscillator is powered from NVCC_PLL.

The system crystal oscillator consists of a Pierce-type structure running off the digital supply. A straight forward biased-inverter implementation is used.

4.2.4.2 OSC32K

This block implements an amplifier that when combined with a suitable quartz crystal and external load capacitors implement a low power oscillator. It also implements a power mux such that it can be powered from either a ~3 V backup battery (VDD_SNVS_IN) or VDD_HIGH_IN such as the oscillator consumes power from VDD_HIGH_IN when that supply is available and transitions to the backup battery when VDD_HIGH_IN is lost.

In addition, if the clock monitor determines that the OSC32K is not present, then the source of the 32 K will automatically switch to a crude internal ring oscillator. The frequency range of this block is approximately 10–45 kHz. It highly depends on the process, voltage, and temperature.

The OSC32k runs from VDD_SNVS_CAP supply, which comes from the VDD_HIGH_IN/VDD_SNVS_IN. The target battery is a ~3 V coin cell. Proper choice of coin cell type is necessary for chosen VDD_HIGH_IN range. Appropriate series resistor (Rs) must be used when connecting the coin cell. Rs depends on the charge current limit that depends on the chosen coin cell. For example, for Panasonic ML621:

Electrical characteristics

- Average Discharge Voltage is 2.5 V
- Maximum Charge Current is 0.6 mA

For a charge voltage of 3.2 V, $R_s = (3.2-2.5)/0.6 \text{ m} = 1.17 \text{ k}$.

Table 18. OSC32K main characteristics

| | Min | Typ | Max | Comments |
|---------------------------|-----|-----------------|----------------|---|
| Fosc | — | 32.768 KHz | — | This frequency is nominal and determined mainly by the crystal selected. 32.0 K would work as well. |
| Current consumption | — | 4 μA | — | The 4 μA is the consumption of the oscillator alone (OSC32k). Total supply consumption will depend on what the digital portion of the RTC consumes. The ring oscillator consumes 1 μA when ring oscillator is inactive, 20 μA when the ring oscillator is running. Another 1.5 μA is drawn from vdd_rtc in the power_detect block. So, the total current is 6.5 μA on vdd_rtc when the ring oscillator is not running. |
| Bias resistor | — | 14 M Ω | — | This integrated bias resistor sets the amplifier into a high gain state. Any leakage through the ESD network, external board leakage, or even a scope probe that is significant relative to this value will debias the amp. The debiasing will result in low gain, and will impact the circuit's ability to start up and maintain oscillations. |
| Crystal Properties | | | | |
| Cload | — | 10 pF | — | Usually crystals can be purchased tuned for different Cloads. This Cload value is typically 1/2 of the capacitances realized on the PCB on either side of the quartz. A higher Cload will decrease oscillation margin, but increases current oscillating through the crystal. |
| ESR | — | 50 k Ω | 100 k Ω | Equivalent series resistance of the crystal. Choosing a crystal with a higher value will decrease the oscillating margin. |

4.3 I/O parameters

This section provide parameters on I/O interfaces.

4.3.1 I/O DC parameters

This section includes the DC parameters of the following I/O types:

- XTALI and RTC_XTALI (Clock Inputs) DC Parameters
- General Purpose I/O (GPIO)

NOTE

The term 'NVCC_XXXX' in this section refers to the associated supply rail of an input or output.

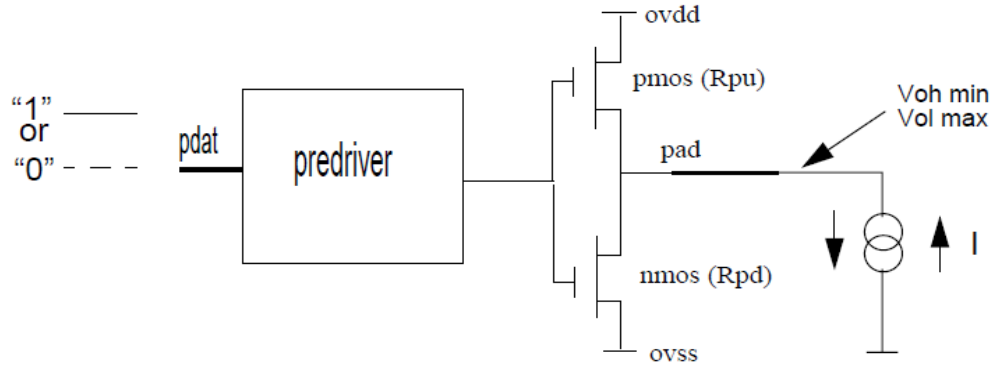


Figure 3. Circuit for parameters Voh and Vol for I/O cells

4.3.1.1 XTALI and RTC_XTALI (clock inputs) DC parameters

Table 19 shows the DC parameters for the clock inputs.

Table 19. XTALI and RTC_XTALI DC parameters¹

| Parameter | Symbol | Test Conditions | Min | Max | Unit |
|---------------------------------------|--------|-----------------|----------------|----------|------|
| XTALI high-level DC input voltage | Vih | — | 0.8 x NVCC_PLL | NVCC_PLL | V |
| XTALI low-level DC input voltage | Vil | — | 0 | 0.2 | V |
| RTC_XTALI high-level DC input voltage | Vih | — | 0.8 | 1.1 | V |
| RTC_XTALI low-level DC input voltage | Vil | — | 0 | 0.2 | V |

¹ The DC parameters are for external clock input only.

4.3.1.2 Single voltage general purpose I/O (GPIO) DC parameters

Table 20 shows DC parameters for GPIO pads. The parameters in Table 20 are guaranteed per the operating ranges in Table 9, unless otherwise noted.

Table 20. Single voltage GPIO DC parameters

| Parameter | Symbol | Test Conditions | Min | Max | Units |
|--|-----------------|--|-----------------|-----|-------|
| High-level output voltage ¹ | V _{OH} | I _{oh} = -0.1 mA (ipp_dse = 001,010) I _{oh} = -1 mA (ipp_dse = 011,100,101,110,111) | NVCC_XXXX - 0.2 | — | V |
| Low-level output voltage ¹ | V _{OL} | I _{ol} = 0.1 mA (ipp_dse = 001,010) I _{ol} = 1 mA (ipp_dse = 011,100,101,110,111) | — | 0.2 | V |

Electrical characteristics

Table 20. Single voltage GPIO DC parameters (continued)

| Parameter | Symbol | Test Conditions | Min | Max | Units |
|---|------------------|---|---------------------------|--|-------|
| High-level output current | I_{OH} | $V_{DDE} = 3.3\text{ V}$, $V_{OH} = V_{DDE} - 0.45\text{ V}$, ipp_dse as follows: 001 010 011 110 101 110 111 | — | -1 -1 -2 -2 -2 -4 -4 | mA |
| Low-level output current | I_{OL} | $V_{DDE} = 3.3\text{ V}$, $V_{OL} = 0.45\text{ V}$, ipp_dse as follows: 001 010 011 110 101 110 111 | — | 1 1 2 2 2 4 4 | mA |
| High-Level input voltage ^{1,2} | V_{IH} | — | $0.7 \times$ NVCC_XXXX | NVCC_XXXX | V |
| Low-Level input voltage ^{1,2} | V_{IL} | — | 0 | $0.3 \times$ NVCC_XXXX | V |
| Input Hysteresis (NVCC_XXXX= 1.8V) | VHYS_LowV DD | NVCC_XXXX = 1.8 V | 250 | — | mV |
| Input Hysteresis (NVCC_XXXX=3.3V) | VHYS_High VDD | NVCC_XXXX = 3.3 V | 250 | — | mV |
| Schmitt trigger V_{T+} ^{2,3} | V_{TH+} | — | $0.5 \times$ NVCC_XXXX | — | mV |
| Schmitt trigger V_{T-} ^{2,3} | V_{TH-} | — | — | $0.5 \times$ NVCC_XXXX | mV |
| Pull-up resistor (22_kΩ PU) | RPU_22K | $V_{in} = 0\text{ V}$ | — | 212 | μA |
| Pull-up resistor (22_kΩ PU) | RPU_22K | $V_{in} = \text{NVCC_XXXX}$ | — | 1 | μA |
| Pull-up resistor (47_kΩ PU) | RPU_47K | $V_{in} = 0\text{ V}$ | — | 100 | μA |
| Pull-up resistor (47_kΩ PU) | RPU_47K | $V_{in} = \text{NVCC_XXXX}$ | — | 1 | μA |
| Pull-up resistor (100_kΩ PU) | RPU_100K | $V_{in} = 0\text{ V}$ | — | 48 | μA |
| Pull-up resistor (100_kΩ PU) | RPU_100K | $V_{in} = \text{NVCC_XXXX}$ | — | 1 | μA |
| Pull-down resistor (100_kΩ PD) | RPD_100K | $V_{in} = \text{NVCC_XXXX}$ | — | 48 | μA |
| Pull-down resistor (100_kΩ PD) | RPD_100K | $V_{in} = 0\text{ V}$ | — | 1 | μA |
| Input current (no PU/PD) | IIN | $V_I = 0$, $V_I = \text{NVCC_XXXX}$ | -1 | 1 | μA |
| Keeper Circuit Resistance | R_Keeper | $V_I = 0.3 \times \text{NVCC_XXXX}$, $V_I = 0.7$ $\times \text{NVCC_XXXX}$ | 105 | 175 | kΩ |

- ¹ Overshoot and undershoot conditions (transitions above NVCC_XXXX and below GND) on switching pads must be held below 0.6 V, and the duration of the overshoot/undershoot must not exceed 10% of the system clock cycle. Overshoot/undershoot must be controlled through printed circuit board layout, transmission line impedance matching, signal line termination, or other methods. Non-compliance to this specification may affect device reliability or cause permanent damage to the device.
- ² To maintain a valid level, the transition edge of the input must sustain a constant slew rate (monotonic) from the current DC level through to the target DC level, V_{il} or V_{ih} . Monotonic input transition time is from 0.1 ns to 1 s.
- ³ Hysteresis of 250 mV is guaranteed over all operating conditions when hysteresis is enabled.

4.3.2 I/O AC parameters

This section includes the AC parameters of the following I/O types:

- General Purpose I/O (GPIO)

Figure 4 shows load circuit for output, and Figure 5 show the output transition time waveform.

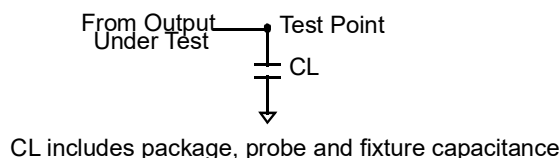


Figure 4. Load circuit for output

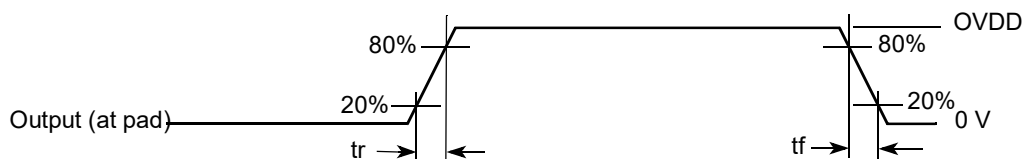


Figure 5. Output transition time waveform

4.3.2.1 General purpose I/O AC parameters

The I/O AC parameters for GPIO in slow and fast modes are presented in the [Table 21](#) and [Table 22](#), respectively. Note that the fast or slow I/O behavior is determined by the appropriate control bits in the IOMUXC control registers.

Electrical characteristics

Table 21. General purpose I/O AC parameters 1.8 V mode

| Parameter | Symbol | Test Condition | Min | Typ | Max | Unit |
|--|--------|--|-----|-----|------------------------|------|
| Output Pad Transition Times, rise/fall (Max Drive, ipp_dse=111) | tr, tf | 15 pF Cload, slow slew rate 15 pF Cload, fast slew rate | — | — | 2.72/2.79 1.51/1.54 | ns |
| Output Pad Transition Times, rise/fall (High Drive, ipp_dse=101) | tr, tf | 15 pF Cload, slow slew rate 15 pF Cload, fast slew rate | — | — | 3.20/3.36 1.96/2.07 | |
| Output Pad Transition Times, rise/fall (Medium Drive, ipp_dse=100) | tr, tf | 15 pF Cload, slow slew rate 15 pF Cload, fast slew rate | — | — | 3.64/3.88 2.27/2.53 | |
| Output Pad Transition Times, rise/fall (Low Drive, ipp_dse=011) | tr, tf | 15 pF Cload, slow slew rate 15 pF Cload, fast slew rate | — | — | 4.32/4.50 3.16/3.17 | |
| Input Transition Times ¹ | trm | — | — | — | 25 | ns |

¹ Hysteresis mode is recommended for inputs with transition times greater than 25 ns.

Table 22. General purpose I/O AC parameters 3.3 V mode

| Parameter | Symbol | Test condition | Min | Typ | Max | Unit |
|--|--------|--|-----|-----|------------------------|------|
| Output Pad Transition Times, rise/fall (Max Drive, ipp_dse=101) | tr, tf | 15 pF Cload, slow slew rate 15 pF Cload, fast slew rate | — | — | 1.70/1.79 1.06/1.15 | ns |
| Output Pad Transition Times, rise/fall (High Drive, ipp_dse=011) | tr, tf | 15 pF Cload, slow slew rate 15 pF Cload, fast slew rate | — | — | 2.35/2.43 1.74/1.77 | |
| Output Pad Transition Times, rise/fall (Medium Drive, ipp_dse=010) | tr, tf | 15 pF Cload, slow slew rate 15 pF Cload, fast slew rate | — | — | 3.13/3.29 2.46/2.60 | |
| Output Pad Transition Times, rise/fall (Low Drive, ipp_dse=001) | tr, tf | 15 pF Cload, slow slew rate 15 pF Cload, fast slew rate | — | — | 5.14/5.57 4.77/5.15 | ns |
| Input Transition Times ¹ | trm | — | — | — | 25 | ns |

¹ Hysteresis mode is recommended for inputs with transition times greater than 25 ns.

4.3.3 Output buffer impedance parameters

This section defines the I/O impedance parameters of the i.MX RT1015 processors for the following I/O types:

- Single Voltage General Purpose I/O (GPIO)

NOTE

GPIO I/O output driver impedance is measured with “long” transmission line of impedance Z_{tl} attached to I/O pad and incident wave launched into transmission line. R_{pu}/R_{pd} and Z_{tl} form a voltage divider that defines specific voltage of incident wave relative to $NVCC_XXXX$. Output driver impedance is calculated from this voltage divider (see [Figure 6](#)).

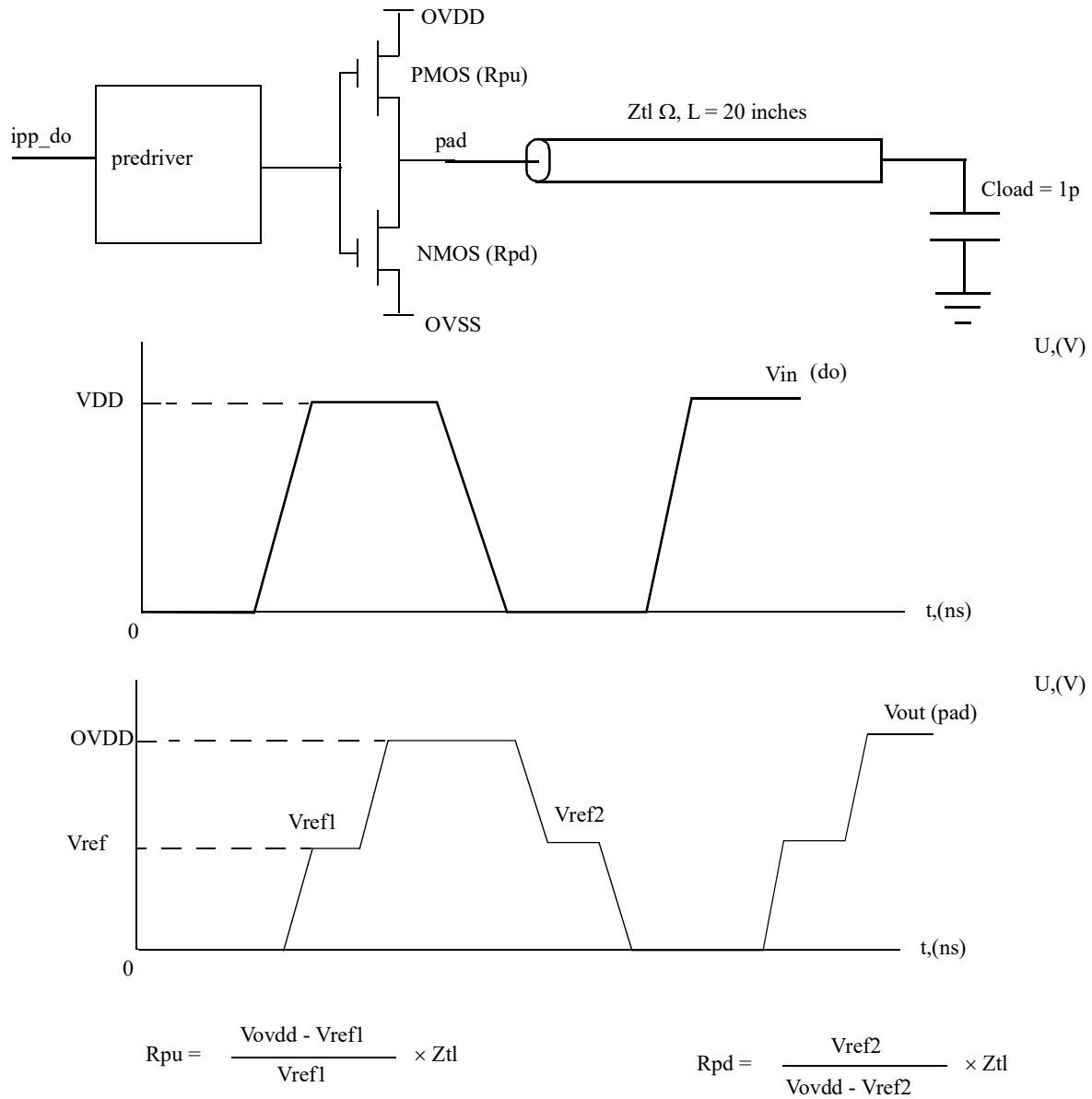


Figure 6. Impedance matching load for measurement

4.3.3.1 Single voltage GPIO output buffer impedance

Table 23 shows the GPIO output buffer impedance (NVCC_XXXX 1.8 V).

Table 23. GPIO output buffer average impedance (NVCC_XXXX 1.8 V)

| Parameter | Symbol | Drive strength (DSE) | Typ value | Unit |
|-------------------------|--------|----------------------|-----------|------|
| Output Driver Impedance | Rdrv | 001 | 260 | Ω |
| | | 010 | 130 | |
| | | 011 | 88 | |
| | | 100 | 65 | |
| | | 101 | 52 | |
| | | 110 | 43 | |
| | | 111 | 37 | |

Table 24 shows the GPIO output buffer impedance (NVCC_XXXX 3.3 V).

Table 24. GPIO Output buffer average impedance (NVCC_XXXX 3.3 V)

| Parameter | Symbol | Drive strength (DSE) | Typ value | Unit |
|-------------------------|--------|----------------------|-----------|------|
| Output Driver Impedance | Rdrv | 001 | 157 | Ω |
| | | 010 | 78 | |
| | | 011 | 53 | |
| | | 100 | 39 | |
| | | 101 | 32 | |
| | | 110 | 26 | |
| | | 111 | 23 | |

4.4 System modules

This section contains the timing and electrical parameters for the modules in the i.MX RT1015 processor.

4.4.1 Reset timings parameters

Figure 7 shows the reset timing and Table 25 lists the timing parameters.

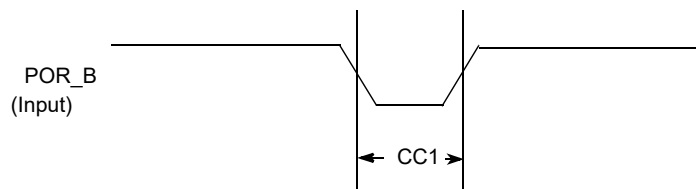


Figure 7. Reset timing diagram

Table 25. Reset timing parameters

| ID | Parameter | Min | Max | Unit |
|-----|---|-----|-----|-----------------|
| CC1 | Duration of POR_B to be qualified as valid. | 1 | — | RTC_XTALI cycle |

4.4.2 WDOG reset timing parameters

Figure 8 shows the WDOG reset timing and Table 26 lists the timing parameters.

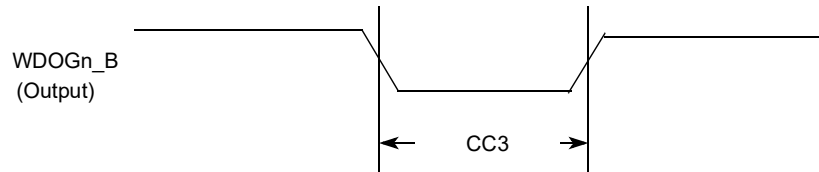


Figure 8. WDOGn_B timing diagram

Table 26. WDOGn_B timing parameters

| ID | Parameter | Min | Max | Unit |
|-----|-------------------------------|-----|-----|-----------------|
| CC3 | Duration of WDOGn_B Assertion | 1 | — | RTC_XTALI cycle |

NOTE

RTC_XTALI is approximately 32 kHz. RTC_XTALI cycle is one period or approximately 30 μ s.

NOTE

WDOGn_B output signals (for each one of the Watchdog modules) do not have dedicated pins, but are muxed out through the IOMUX. See the IOMUX manual for detailed information.

4.4.3 SCAN JTAG Controller (SJC) timing parameters

Figure 9 depicts the SJC test clock input timing. Figure 10 depicts the SJC boundary scan timing. Figure 11 depicts the SJC test access port. Signal parameters are listed in Table 27.

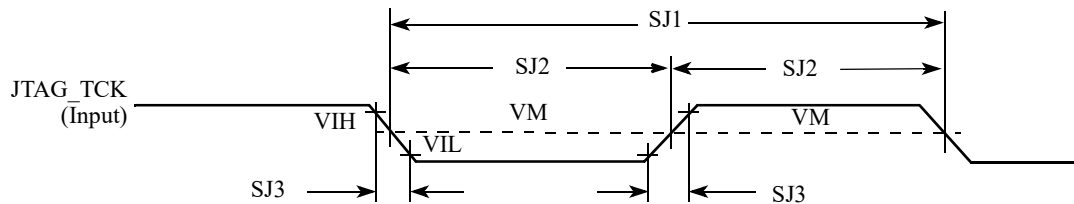


Figure 9. Test clock input timing diagram

Electrical characteristics

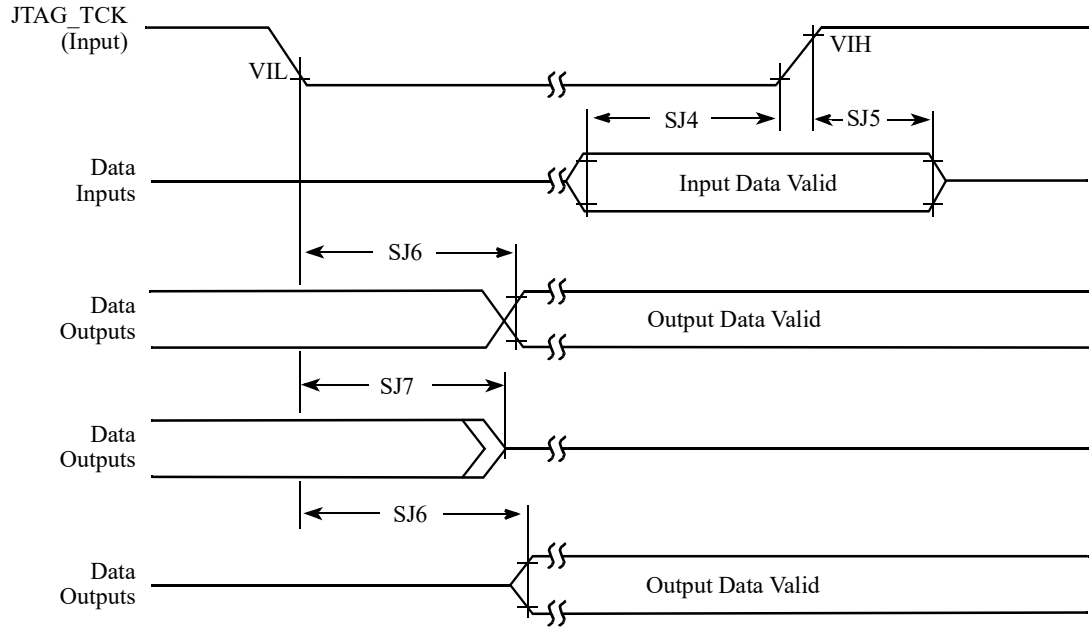


Figure 10. Boundary scan (JTAG) timing diagram

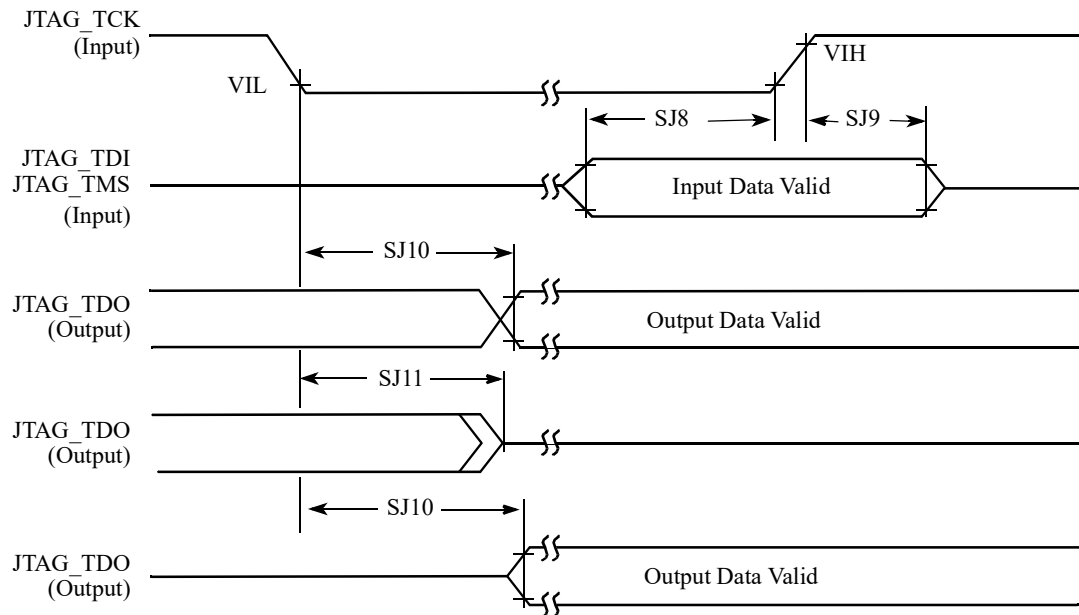


Figure 11. Test access port timing diagram

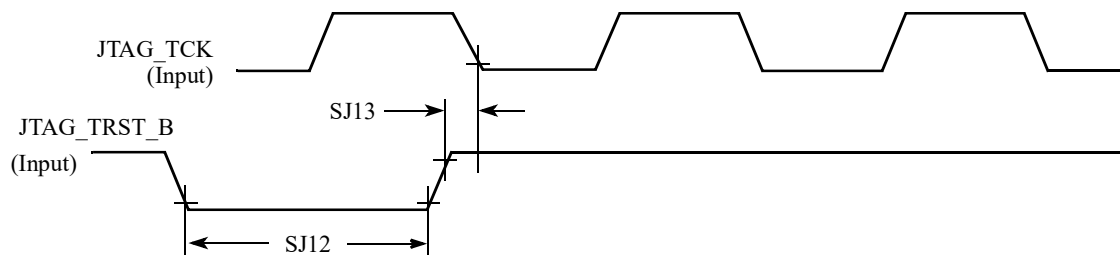


Figure 12. JTAG_TRST_B timing diagram

Table 27. JTAG timing

| ID | Parameter ^{1,2} | All frequencies | | Unit |
|-----|--|-----------------|-----|------|
| | | Min | Max | |
| SJ0 | JTAG_TCK frequency of operation $1/(3 \cdot T_{DC})^1$ | 0.001 | 22 | MHz |
| SJ1 | JTAG_TCK cycle time in crystal mode | 45 | — | ns |
| SJ2 | JTAG_TCK clock pulse width measured at V_M^2 | 22.5 | — | ns |
| SJ3 | JTAG_TCK rise and fall times | — | 3 | ns |
| SJ4 | Boundary scan input data set-up time | 5 | — | ns |
| SJ5 | Boundary scan input data hold time | 24 | — | ns |
| SJ6 | JTAG_TCK low to output data valid | — | 40 | ns |
| SJ7 | JTAG_TCK low to output high impedance | — | 40 | ns |
| SJ8 | JTAG_TMS, JTAG_TDI data set-up time | 5 | — | ns |

Table 27. JTAG timing (continued)

| ID | Parameter ^{1,2} | All frequencies | | Unit |
|------|---|-----------------|-----|------|
| | | Min | Max | |
| SJ9 | JTAG_TMS, JTAG_TDI data hold time | 25 | — | ns |
| SJ10 | JTAG_TCK low to JTAG_TDO data valid | — | 44 | ns |
| SJ11 | JTAG_TCK low to JTAG_TDO high impedance | — | 44 | ns |
| SJ12 | JTAG_TRST_B assert time | 100 | — | ns |
| SJ13 | JTAG_TRST_B set-up time to JTAG_TCK low | 40 | — | ns |

¹ T_{DC} = target frequency of SJC

² V_M = mid-point voltage

4.4.4 Debug trace timing specifications

Table 28. Debug trace operating behaviors

| Symbol | Description | Min | Max | Unit |
|--------|--------------------------------------|------|-----|------|
| T1 | ARM_TRACE_CLK frequency of operation | — | 70 | MHz |
| T2 | ARM_TRACE_CLK period | 1/T1 | — | MHz |
| T3 | Low pulse width | 6 | — | ns |
| T4 | High pulse width | 6 | — | ns |
| T5 | Clock and data rise time | — | 1 | ns |
| T6 | Clock and data fall time | — | 1 | ns |
| T7 | Data setup | 2 | — | ns |
| T8 | Data hold | 0.7 | — | ns |

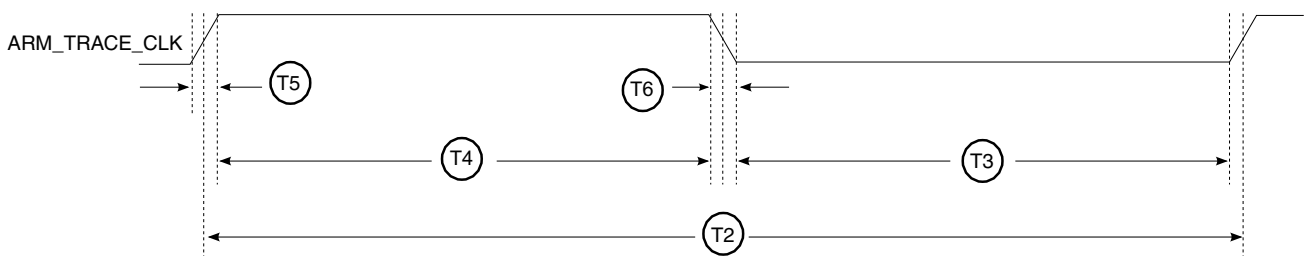


Figure 13. ARM_TRACE_CLK specifications

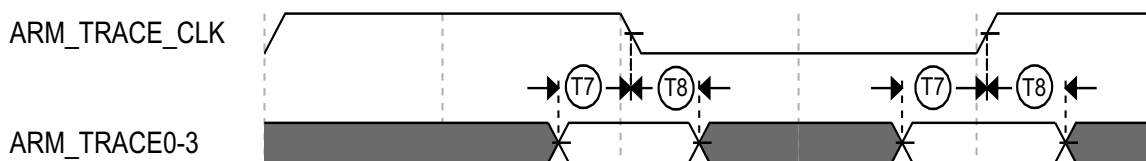


Figure 14. Trace data specifications

4.5 External memory interface

The following sections provide information about external memory interfaces. FlexSPI parameters Measurements are with a load 15 pf and input slew rate of 1 V/ns.

4.5.1 FlexSPI input/read timing

There are four sources for the internal sample clock for FlexSPI read data:

- Dummy read strobe generated by FlexSPI controller and looped back internally (FlexSPI_n_MCR0[RXCLKSRC] = 0x0)
- Dummy read strobe generated by FlexSPI controller and looped back through the DQS pad (FlexSPI_n_MCR0[RXCLKSRC] = 0x1)
- Read strobe provided by memory device and input from DQS pad (FlexSPI_n_MCR0[RXCLKSRC] = 0x3)

The following sections describe input signal timing for each of these four internal sample clock sources.

4.5.1.0.1 SDR mode with FlexSPI_n_MCR0[RXCLKSRC] = 0x0, 0x1

Table 29. FlexSPI input timing in SDR mode where FlexSPI_n_MCR0[RXCLKSRC] = 0X0

| Symbol | Parameter | Min | Max | Unit |
|-----------------|------------------------------|------|-----|------|
| — | Frequency of operation | — | 60 | MHz |
| T _{IS} | Setup time for incoming data | 8.67 | — | ns |
| T _{IH} | Hold time for incoming data | 0 | — | ns |

Table 30. FlexSPI input timing in SDR mode where FlexSPI_n_MCR0[RXCLKSRC] = 0X1

| Symbol | Parameter | Min | Max | Unit |
|-----------------|------------------------------|-----|-----|------|
| — | Frequency of operation | — | 133 | MHz |
| T _{IS} | Setup time for incoming data | 2 | — | ns |
| T _{IH} | Hold time for incoming data | 1 | — | ns |

Electrical characteristics

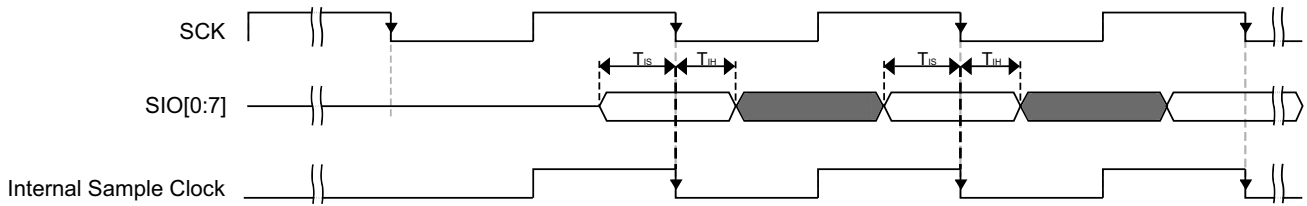


Figure 15. FlexSPI input timing in SDR mode where FlexSPI_n_MCR0[RXCLKSRC] = 0X0, 0X1

NOTE

Timing shown is based on the memory generating read data on the SCK falling edge, and FlexSPI controller sampling read data on the falling edge.

4.5.1.0.2 SDR mode with FlexSPI_n_MCR0[RXCLKSRC] = 0x3

There are two cases when the memory provides both read data and the read strobe in SDR mode:

- A1–Memory generates both read data and read strobe on SCK rising edge (or falling edge)
- A2–Memory generates read data on SCK falling edge and generates read strobe on SCK rising edge

Table 31. FlexSPI input timing in SDR mode where FlexSPI_n_MCR0[RXCLKSRC] = 0x3 (Case A1)

| Symbol | Parameter | Value | | Unit |
|---|--|-------|-----|------|
| | | Min | Max | |
| — | Frequency of operation | — | 166 | MHz |
| T _{SCKD} | Time from SCK to data valid | — | — | ns |
| T _{SCKDQS} | Time from SCK to DQS | — | — | ns |
| T _{SCKD} - T _{SCKDQS} | Time delta between T _{SCKD} and T _{SCKDQS} | -2 | 2 | ns |

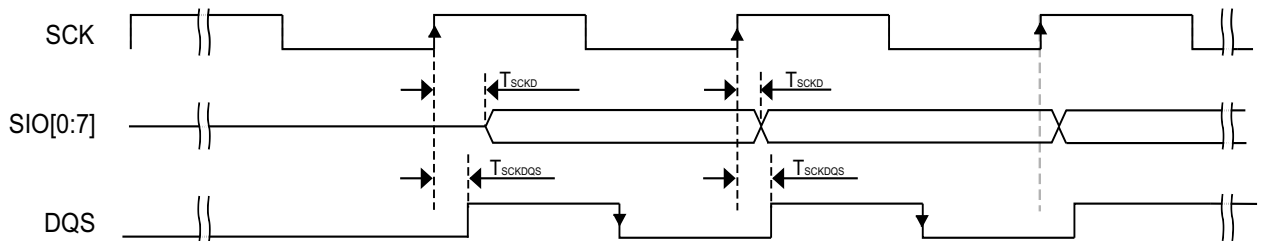


Figure 16. FlexSPI input timing in SDR mode where FlexSPI_n_MCR0[RXCLKSRC] = 0X3 (Case A1)

NOTE

Timing shown is based on the memory generating read data and read strobe on the SCK rising edge. The FlexSPI controller samples read data on the DQS falling edge.

Table 32. FlexSPI input timing in SDR mode where FlexSPI_n_MCR0[RXCLKSRC] = 0x3 (Case A2)

| Symbol | Parameter | Value | | Unit |
|---|--|-------|-----|------|
| | | Min | Max | |
| — | Frequency of operation | — | 166 | MHz |
| T _{SCKD} | Time from SCK to data valid | — | — | ns |
| T _{SCKDQS} | Time from SCK to DQS | — | — | ns |
| T _{SCKD} - T _{SCKDQS} | Time delta between T _{SCKD} and T _{SCKDQS} | -2 | 2 | ns |

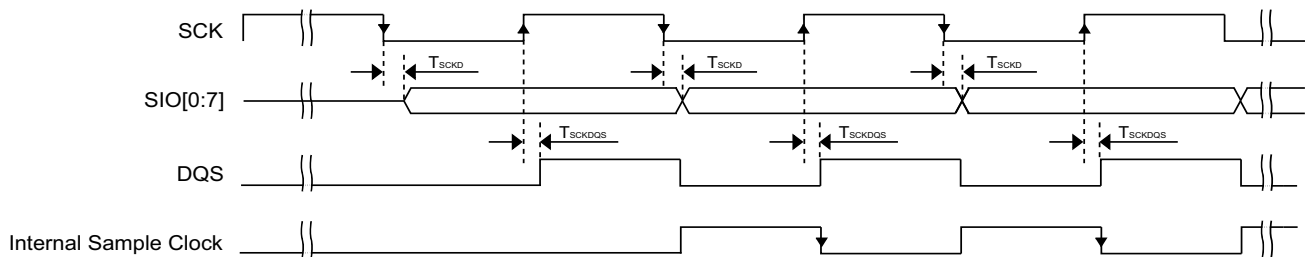


Figure 17. FlexSPI input timing in SDR mode where FlexSPI_n_MCR0[RXCLKSRC] = 0X3 (Case A2)

NOTE

Timing shown is based on the memory generating read data on the SCK falling edge and read strobe on the SCK rising edge. The FlexSPI controller samples read data on a half cycle delayed DQS falling edge.

4.5.1.0.3 DDR mode with FlexSPI_n_MCR0[RXCLKSRC] = 0x0, 0x1

Table 33. FlexSPI input timing in DDR mode where FlexSPI_n_MCR0[RXCLKSRC] = 0x0

| Symbol | Parameter | Min | Max | Unit |
|-----------------|------------------------------|------|-----|------|
| — | Frequency of operation | — | 30 | MHz |
| T _{IS} | Setup time for incoming data | 8.67 | — | ns |
| T _{IH} | Hold time for incoming data | 0 | — | ns |

Table 34. FlexSPI input timing in DDR mode where FlexSPI_n_MCR0[RXCLKSRC] = 0x1

| Symbol | Parameter | Min | Max | Unit |
|-----------------|------------------------------|-----|-----|------|
| — | Frequency of operation | — | 66 | MHz |
| T _{IS} | Setup time for incoming data | 2 | — | ns |
| T _{IH} | Hold time for incoming data | 1 | — | ns |

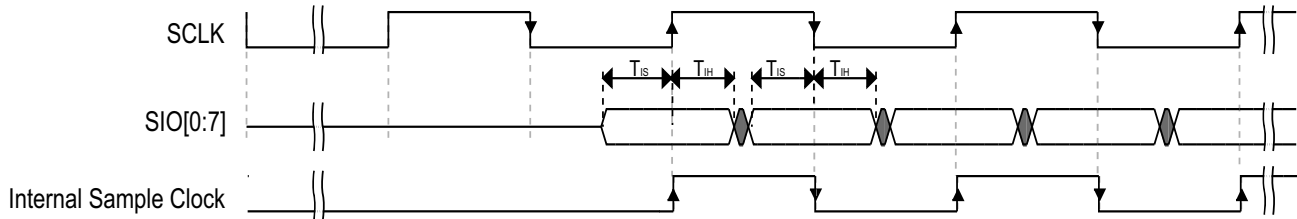


Figure 18. FlexSPI input timing in DDR mode where FlexSPI_n_MCR0[RXCLKSRC] = 0x0, 0x1

4.5.1.0.4 DDR mode with FlexSPI_n_MCR0[RXCLKSRC] = 0x3

There are two cases when the memory provides both read data and the read strobe in DDR mode:

- B1–Memory generates both read data and read strobe on SCK edge
- B2–Memory generates read data on SCK edge and generates read strobe on SCK2 edge

Table 35. FlexSPI input timing in DDR mode where FlexSPI_n_MCR0[RXCLKSRC] = 0x3 (Case B1)

| Symbol | Parameter | Min | Max | Unit |
|---|--|-----|-----|------|
| — | Frequency of operation | — | 166 | MHz |
| T _{SCKD} | Time from SCK to data valid | — | — | ns |
| T _{SCKDQS} | Time from SCK to DQS | — | — | ns |
| T _{SCKD} - T _{SCKDQS} | Time delta between T _{SCKD} and T _{SCKDQS} | -1 | 1 | ns |

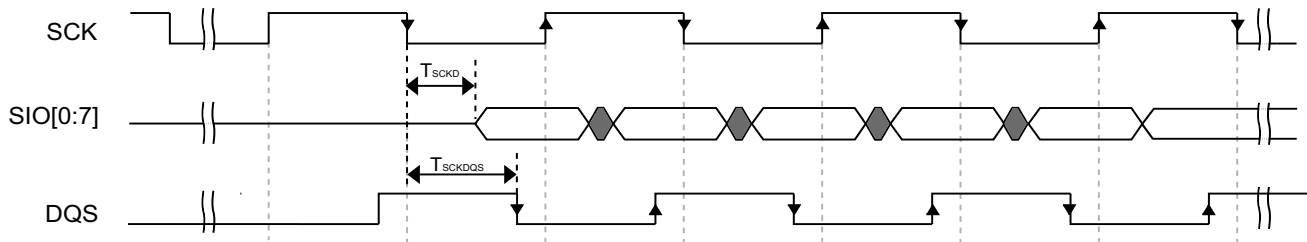


Figure 19. FlexSPI input timing in DDR mode where FlexSPI_n_MCR0[RXCLKSRC] = 0x3 (Case B1)

Table 36. FlexSPI input timing in DDR mode where FlexSPI_n_MCR0[RXCLKSRC] = 0x3 (Case B2)

| Symbol | Parameter | Min | Max | Unit |
|---|--|-----|-----|------|
| — | Frequency of operation | — | 166 | MHz |
| T _{SCKD} | Time from SCK to data valid | — | — | ns |
| T _{SCKD} - T _{SCKDQS} | Time delta between T _{SCKD} and T _{SCKDQS} | -1 | 1 | ns |

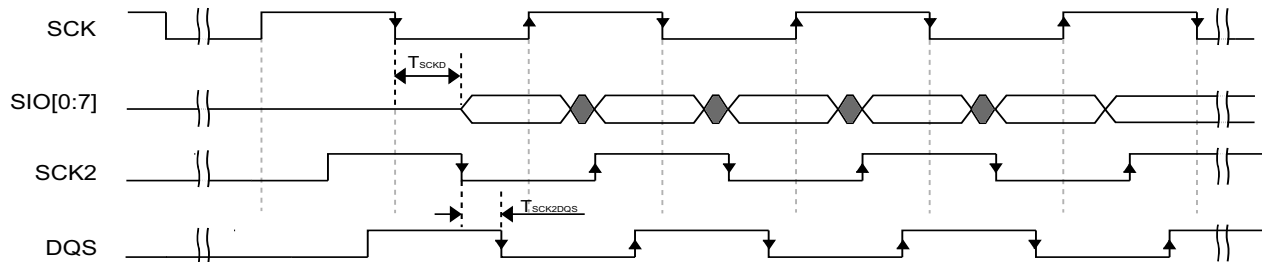


Figure 20. FlexSPI input timing in DDR mode where FlexSPI_n_MCR0[RXCLKSRC] = 0x3 (Case B2)

4.5.1.1 FlexSPI output/write timing

The following sections describe output signal timing for the FlexSPI controller including control signals and data outputs.

4.5.1.1.1 SDR mode

Table 37. FlexSPI output timing in SDR mode

| Symbol | Parameter | Min | Max | Unit |
|------------------|------------------------|-----|------------------|------|
| — | Frequency of operation | — | 166 ¹ | MHz |
| T _{ck} | SCK clock period | 6.0 | — | ns |
| T _{DVO} | Output data valid time | — | 1 | ns |
| T _{DHO} | Output data hold time | -1 | — | ns |

Electrical characteristics

Table 37. FlexSPI output timing in SDR mode (continued)

| Symbol | Parameter | Min | Max | Unit |
|-----------|-------------------------------|-----------------------|-----|------|
| T_{CSS} | Chip select output setup time | $3 \times T_{CK} - 1$ | — | ns |
| T_{CSH} | Chip select output hold time | $3 \times T_{CK} + 2$ | — | ns |

¹ The actual maximum frequency supported is limited by the FlexSPI_n_MCR0[RXCLKSRC] configuration used. Please refer to the FlexSPI SDR input timing specifications.

NOTE

T_{CSS} and T_{CSH} are configured by the FlexSPI_n_FLSHAxCR1 register, the default values are shown above. Please refer to the *i.MX RT1015 Reference Manual (IMXRT1015RM)* for more details.

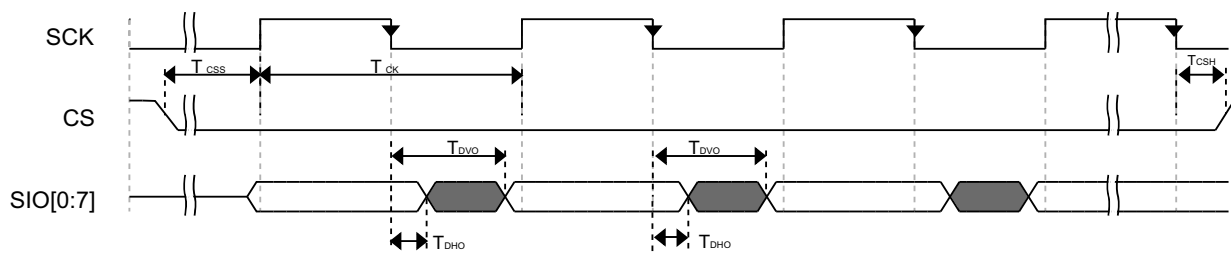


Figure 21. FlexSPI output timing in SDR mode

4.5.1.1.2 DDR mode

Table 38. FlexSPI output timing in DDR mode

| Symbol | Parameter | Min | Max | Unit |
|-----------|---|-----------------------------|-----|------|
| — | Frequency of operation ¹ | — | 166 | MHz |
| T_{ck} | SCK clock period (FlexSPI _n _MCR0[RXCLKSRC] = 0x0) | 6.0 | — | ns |
| T_{DVO} | Output data valid time | — | 2.2 | ns |
| T_{DHO} | Output data hold time | 0.8 | — | ns |
| T_{CSS} | Chip select output setup time | $3 \times T_{CK} / 2 - 0.7$ | — | ns |
| T_{CSH} | Chip select output hold time | $3 \times T_{CK} / 2 + 0.8$ | — | ns |

¹ The actual maximum frequency supported is limited by the FlexSPI_n_MCR0[RXCLKSRC] configuration used. Please refer to the FlexSPI SDR input timing specifications.

NOTE

T_{CSS} and T_{CSH} are configured by the FlexSPI_n_FLSHAxCR1 register, the default values are shown above. Please refer to the *i.MX RT1015 Reference Manual (IMXRT1015RM)* for more details.

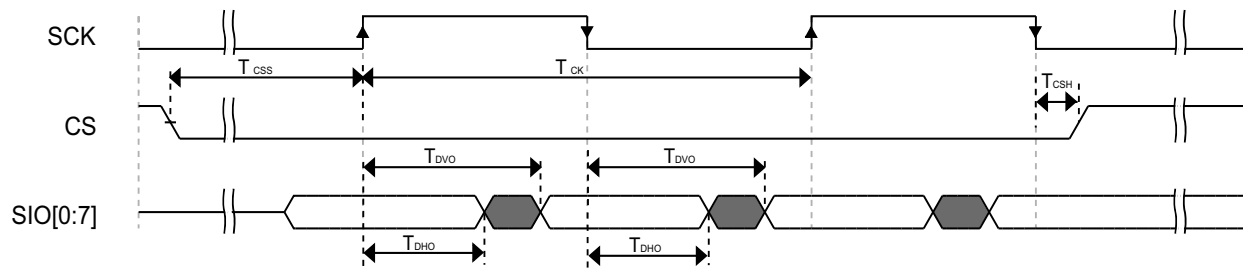


Figure 22. FlexSPI output timing in DDR mode

4.6 Audio

This section provide information about SAI/I2S and SPDIF.

4.6.1 SAI/I2S switching specifications

This section provides the AC timings for the SAI in master (clocks driven) and slave (clocks input) modes. All timings are given for non-inverted serial clock polarity ($\text{SAI_TCR}[\text{TSCKP}] = 0$, $\text{SAI_RCR}[\text{RSCKP}] = 0$) and non-inverted frame sync ($\text{SAI_TCR}[\text{TFSI}] = 0$, $\text{SAI_RCR}[\text{RFSI}] = 0$). If the polarity of the clock and/or the frame sync have been inverted, all the timings remain valid by inverting the clock signal (SAI_BCLK) and/or the frame sync (SAI_FS) shown in the figures below.

Table 39. Master mode SAI timing

| Num | Characteristic | Min | Max | Unit |
|-----|--|---------------------------|-----|-------------|
| S1 | SAI_MCLK cycle time | $2 \times t_{\text{sys}}$ | — | ns |
| S2 | SAI_MCLK pulse width high/low | 40% | 60% | MCLK period |
| S3 | SAI_BCLK cycle time | $4 \times t_{\text{sys}}$ | — | ns |
| S4 | SAI_BCLK pulse width high/low | 40% | 60% | BCLK period |
| S5 | SAI_BCLK to SAI_FS output valid | — | 15 | ns |
| S6 | SAI_BCLK to SAI_FS output invalid | 0 | — | ns |
| S7 | SAI_BCLK to SAI_TXD valid | — | 15 | ns |
| S8 | SAI_BCLK to SAI_TXD invalid | 0 | — | ns |
| S9 | SAI_RXD/SAI_FS input setup before SAI_BCLK | 15 | — | ns |
| S10 | SAI_RXD/SAI_FS input hold after SAI_BCLK | 0 | — | ns |

Electrical characteristics

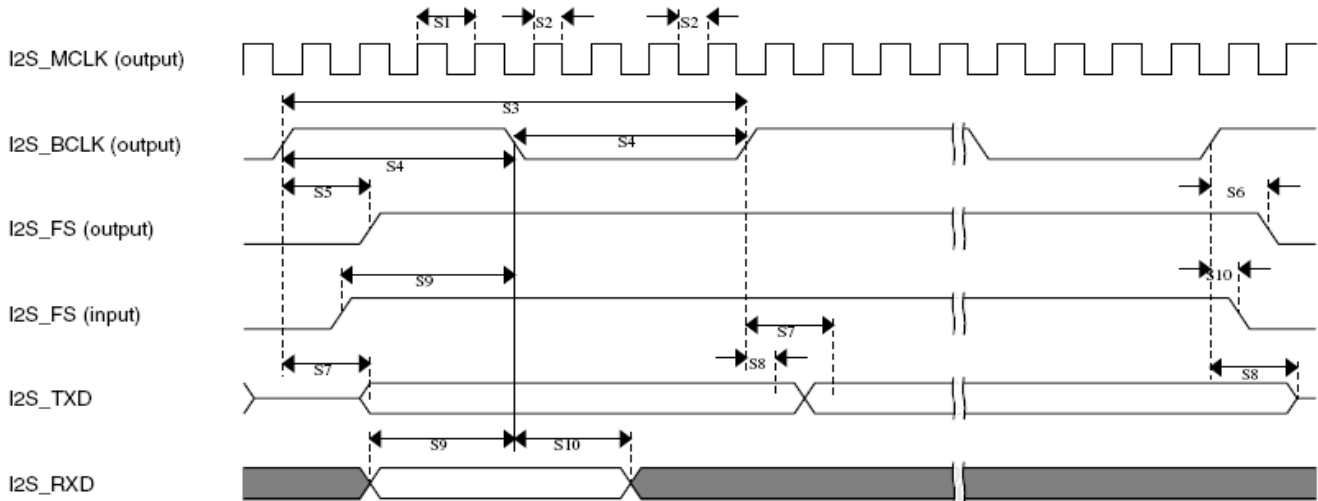


Figure 23. SAI timing—master modes

Table 40. Slave mode SAI timing

| Num | Characteristic | Min | Max | Unit |
|-----|---|--------------------|-----|-------------|
| S11 | SAI_BCLK cycle time (input) | $4 \times t_{sys}$ | — | ns |
| S12 | SAI_BCLK pulse width high/low (input) | 40% | 60% | BCLK period |
| S13 | SAI_FS input setup before SAI_BCLK | 10 | — | ns |
| S14 | SAI_FA input hold after SAI_BCLK | 2 | — | ns |
| S15 | SAI_BCLK to SAI_TXD/SAI_FS output valid | — | 20 | ns |
| S16 | SAI_BCLK to SAI_TXD/SAI_FS output invalid | 0 | — | ns |
| S17 | SAI_RXD setup before SAI_BCLK | 10 | — | ns |
| S18 | SAI_RXD hold after SAI_BCLK | 2 | — | ns |

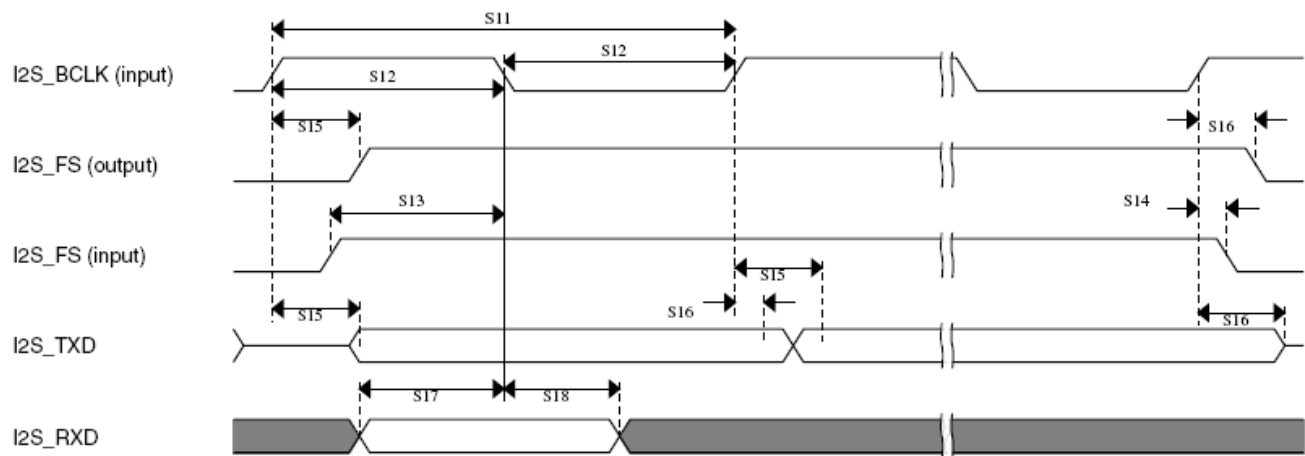


Figure 24. SAI timing—slave modes

4.6.2 SPDIF timing parameters

The Sony/Philips Digital Interconnect Format (SPDIF) data is sent using the bi-phase marking code. When encoding, the SPDIF data signal is modulated by a clock that is twice the bit rate of the data signal.

Table 41 and Figure 25 and Figure 26 show SPDIF timing parameters for the Sony/Philips Digital Interconnect Format (SPDIF), including the timing of the modulating Rx clock (SPDIF_SR_CLK) for SPDIF in Rx mode and the timing of the modulating Tx clock (SPDIF_ST_CLK) for SPDIF in Tx mode.

Table 41. SPDIF timing parameters

| Characteristics | Symbol | Timing parameter range | | Unit |
|--|--------|------------------------|------|------|
| | | Min | Max | |
| SPDIF_IN Skew: asynchronous inputs, no specs apply | — | — | 0.7 | ns |
| SPDIF_OUT output (Load = 50pf) | — | — | 1.5 | ns |
| • Skew | — | — | 24.2 | |
| • Transition rising | — | — | 31.3 | |
| SPDIF_OUT1 output (Load = 30pf) | — | — | 1.5 | ns |
| • Skew | — | — | 13.6 | |
| • Transition rising | — | — | 18.0 | |
| Modulating Rx clock (SPDIF_SR_CLK) period | srckp | 40.0 | — | ns |
| SPDIF_SR_CLK high period | srckph | 16.0 | — | ns |
| SPDIF_SR_CLK low period | srckpl | 16.0 | — | ns |
| Modulating Tx clock (SPDIF_ST_CLK) period | stckp | 40.0 | — | ns |
| SPDIF_ST_CLK high period | stckph | 16.0 | — | ns |
| SPDIF_ST_CLK low period | stckpl | 16.0 | — | ns |

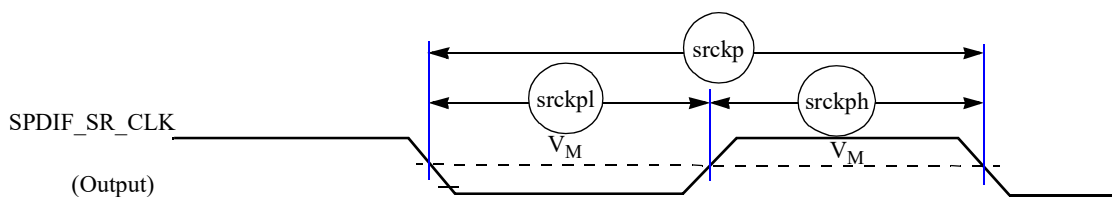


Figure 25. SPDIF_SR_CLK timing diagram

Electrical characteristics

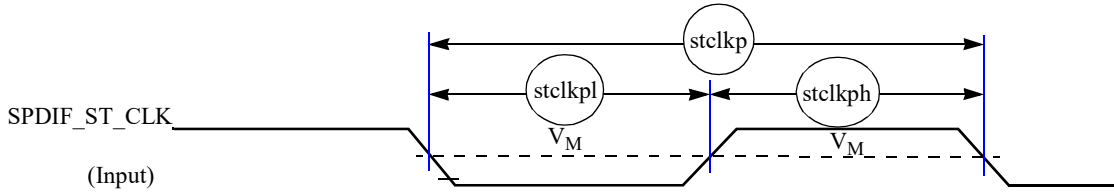


Figure 26. SPDIF_ST_CLK timing diagram

4.7 Analog

The following sections provide information about analog interfaces.

4.7.1 DCDC

Table 42 introduces the DCDC electrical specification.

Table 42. DCDC electrical specifications

| Mode | Buck mode only, one output | Notes |
|----------------------------|--|---|
| Input voltage | 3.3 V | ± 10% |
| Output voltage | 1.1 V | Configurable 0.8 ~ 1.575 with 25 mV one step |
| Max loading | 500 mA | — |
| Loading in low power modes | 200 µA ~ 30 mA | — |
| Efficiency | 90% max | @150 mA |
| Low power mode | Open loop mode | Ripple is about 15 mV |
| Run mode | <ul style="list-style-type: none"> Always continuous mode Support discontinuous mode | Configurable by register |
| Inductor | 4.7 µH | — |
| Capacitor | 33 µF | — |
| Over voltage protection | 1.6 V | Detect VDDSOC, when the voltage is higher than 1.6 V, shutdown DCDC. |
| Over Current protection | 1 A | Detect the peak current <ul style="list-style-type: none"> Run mode: when the current is larger than 1 A, shutdown DCDC. Stop mode: when the current is larger than 250 mA, stop charging the inductor. |
| Low battery detection | 2.6 V | Detect the battery, when battery is lower than 2.6 V, shutdown DCDC. |

4.7.2 A/D converter

This section introduces information about A/D converter.

4.7.2.1 12-bit ADC electrical characteristics

The section provide information about 12-bit ADC electrical characteristics.

4.7.2.1.1 12-bit ADC operating conditions

Table 43. 12-bit ADC operating conditions

| Characteristic | Conditions | Symb | Min | Typ ¹ | Max | Unit | Comment |
|---|--|-------------------|----------|------------------|-----------|-------|---------------------------------|
| Supply voltage | Absolute | V_{DDA} | 3.0 | - | 3.6 | V | — |
| | Delta to VDD (VDD-VDDA) ² | ΔV_{DDA} | -100 | 0 | 100 | mV | — |
| Ground voltage | Delta to VSS (VSS-VSSAD) | ΔV_{SSAD} | -100 | 0 | 100 | mV | — |
| Ref Voltage High | — | V_{DDA} | 1.13 | V_{DDA} | V_{DDA} | V | — |
| Ref Voltage Low | — | V_{SS} | V_{SS} | V_{SS} | V_{SS} | V | — |
| Input Voltage | — | V_{ADIN} | V_{SS} | — | V_{DDA} | V | — |
| Input Capacitance | 8/10/12 bit modes | C_{ADIN} | — | 1.5 | 2 | pF | — |
| Input Resistance | ADLPC=0, ADHSC=1 | R_{ADIN} | — | 5 | 7 | kohms | — |
| | ADLPC=0, ADHSC=0 | | — | 12.5 | 15 | kohms | — |
| | ADLPC=1, ADHSC=0 | | — | 25 | 30 | kohms | — |
| Analog Source Resistance | 12 bit mode $f_{ADCK} = 40\text{MHz}$ ADLSMP=0, ADSTS=10, ADHSC=1 | R_{AS} | — | — | 1 | kohms | $T_{\text{samp}}=150\text{ ns}$ |
| R_{AS} depends on Sample Time Setting (ADLSMP, ADSTS) and ADC Power Mode (ADHSC, ADLPC). See charts for Minimum Sample Time vs R_{AS} | | | | | | | |
| ADC Conversion Clock Frequency | ADLPC=0, ADHSC=1 12 bit mode | f_{ADCK} | 4 | — | 40 | MHz | — |
| | ADLPC=0, ADHSC=0 12 bit mode | | 4 | — | 30 | MHz | — |
| | ADLPC=1, ADHSC=0 12 bit mode | | 4 | — | 20 | MHz | — |

¹ Typical values assume $V_{DDA} = 3.0\text{ V}$, $\text{Temp} = 25^\circ\text{C}$, $f_{ADCK}=20\text{ MHz}$ unless otherwise stated. Typical values are for reference only and are not tested in production.

² DC potential differences

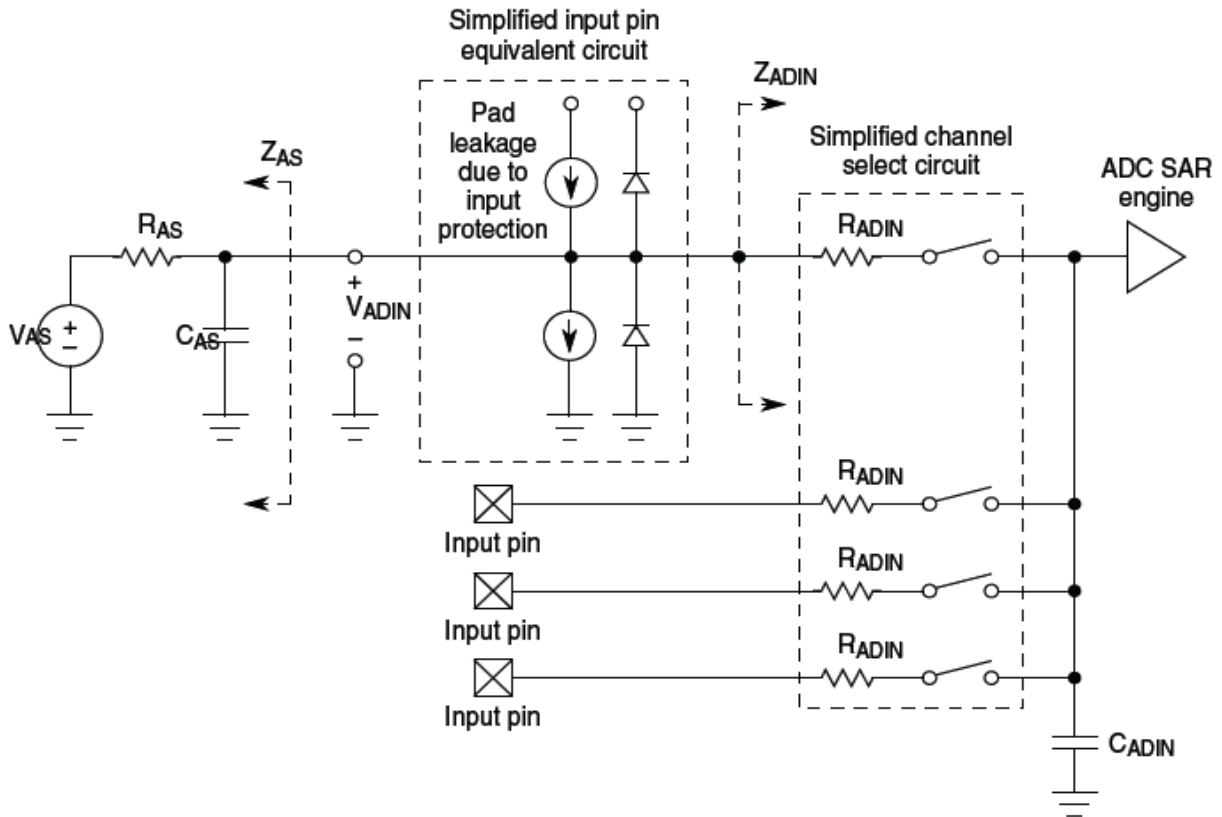


Figure 27. 12-bit ADC input impedance equivalency diagram

12-bit ADC characteristics

Table 44. 12-bit ADC characteristics ($V_{REFH} = V_{DDA}$, $V_{REFL} = V_{SSAD}$)

| Characteristic | Conditions ¹ | Symb | Min | Typ ² | Max | Unit | Comment |
|-------------------------------|-------------------------|-------------|-----|------------------|-----|---------------|----------------------------------|
| Supply Current | ADLPC=1, ADHSC=0 | I_{DDA} | — | 250 | — | μA | ADLSMP = 0, ADSTS = 10, ADCO = 1 |
| | ADLPC=0, ADHSC=0 | | | 350 | | | |
| | ADLPC=0, ADHSC=1 | | | 400 | | | |
| Supply Current | Stop, Reset, Module Off | I_{DDA} | — | 0.01 | 0.8 | μA | — |
| ADC Asynchronous Clock Source | ADHSC=0 | f_{ADACK} | — | 10 | — | MHz | $t_{ADACK} = 1/f_{ADACK}$ |
| | ADHSC=1 | | | 20 | | | |

Table 44. 12-bit ADC characteristics ($V_{REFH} = V_{DDA}$, $V_{REFL} = V_{SSAD}$) (continued)

| Characteristic | Conditions ¹ | Symb | Min | Typ ² | Max | Unit | Comment |
|-------------------|-------------------------|-------|-----|------------------|-----|--------|---------|
| Sample Cycles | ADLSMP=0, ADSTS=00 | Csamp | — | 2 | — | cycles | — |
| | ADLSMP=0, ADSTS=01 | | | 4 | | | |
| | ADLSMP=0, ADSTS=10 | | | 6 | | | |
| | ADLSMP=0, ADSTS=11 | | | 8 | | | |
| | ADLSMP=1, ADSTS=00 | | | 12 | | | |
| | ADLSMP=1, ADSTS=01 | | | 16 | | | |
| | ADLSMP=1, ADSTS=10 | | | 20 | | | |
| | ADLSMP=1, ADSTS=11 | | | 24 | | | |
| Conversion Cycles | ADLSMP=0 ADSTS=00 | Cconv | — | 28 | — | cycles | — |
| | ADLSMP=0 ADSTS=01 | | | 30 | | | |
| | ADLSMP=0 ADSTS=10 | | | 32 | | | |
| | ADLSMP=0 ADSTS=11 | | | 34 | | | |
| | ADLSMP=1 ADSTS=00 | | | 38 | | | |
| | ADLSMP=1 ADSTS=01 | | | 42 | | | |
| | ADLSMP=1 ADSTS=10 | | | 46 | | | |
| | ADLSMP=1, ADSTS=11 | | | 50 | | | |

Electrical characteristics

Table 44. 12-bit ADC characteristics ($V_{REFH} = V_{DDA}$, $V_{REFL} = V_{SSAD}$) (continued)

| Characteristic | Conditions ¹ | Symb | Min | Typ ² | Max | Unit | Comment |
|---------------------------------|-------------------------|-----------------|----------------------------|------------------|-----|--|---------------------|
| Conversion Time | ADLSMP=0 ADSTS=00 | Tconv | — | 0.7 | — | μs | Fadc = 40 MHz |
| | ADLSMP=0 ADSTS=01 | | | 0.75 | | | |
| | ADLSMP=0 ADSTS=10 | | | 0.8 | | | |
| | ADLSMP=0 ADSTS=11 | | | 0.85 | | | |
| | ADLSMP=1 ADSTS=00 | | | 0.95 | | | |
| | ADLSMP=1 ADSTS=01 | | | 1.05 | | | |
| | ADLSMP=1 ADSTS=10 | | | 1.15 | | | |
| | ADLSMP=1, ADSTS=11 | | | 1.25 | | | |
| Total Unadjusted Error | 12 bit mode | TUE | — | 3.4 | — | LSB 1 LSB = ($V_{REFH} - V_{REFL}$)/2 N | AVGE = 1, AVGS = 11 |
| | 10 bit mode | | | 1.5 | | | |
| | 8 bit mode | | | 1.2 | | | |
| Differential Non-Linearity | 12 bit mode | DNL | — | 0.76 | — | LSB | AVGE = 1, AVGS = 11 |
| | 10bit mode | | | 0.36 | | | |
| | 8 bit mode | | | 0.14 | | | |
| Integral Non-Linearity | 12 bit mode | INL | — | 2.78 | — | LSB | AVGE = 1, AVGS = 11 |
| | 10bit mode | | | 0.61 | | | |
| | 8 bit mode | | | 0.14 | | | |
| Zero-Scale Error | 12 bit mode | E _{ZS} | — | -1.14 | — | LSB | AVGE = 1, AVGS = 11 |
| | 10bit mode | | | -0.25 | | | |
| | 8 bit mode | | | -0.19 | | | |
| Full-Scale Error | 12 bit mode | E _{FS} | — | -1.06 | — | LSB | AVGE = 1, AVGS = 11 |
| | 10bit mode | | | -0.03 | | | |
| | 8 bit mode | | | -0.02 | | | |
| Effective Number of Bits | 12 bit mode | ENOB | 10.1 | 10.7 | — | Bits | AVGE = 1, AVGS = 11 |
| Signal to Noise plus Distortion | See ENOB | SINAD | SINAD = 6.02 x ENOB + 1.76 | | | dB | AVGE = 1, AVGS = 11 |

¹ All accuracy numbers assume the ADC is calibrated with $V_{REFH}=V_{DDAD}$

² Typical values assume $V_{DDAD} = 3.0\text{ V}$, $\text{Temp} = 25^\circ\text{C}$, $F_{\text{adck}} = 20\text{ MHz}$ unless otherwise stated. Typical values are for reference only and are not tested in production.

NOTE

The ADC electrical spec is met with the calibration enabled configuration.

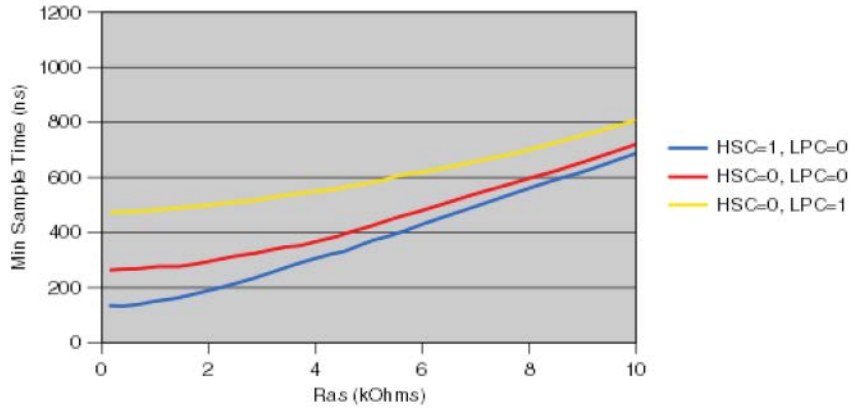


Figure 28. Minimum Sample Time Vs Ras (Cas = 2 pF)

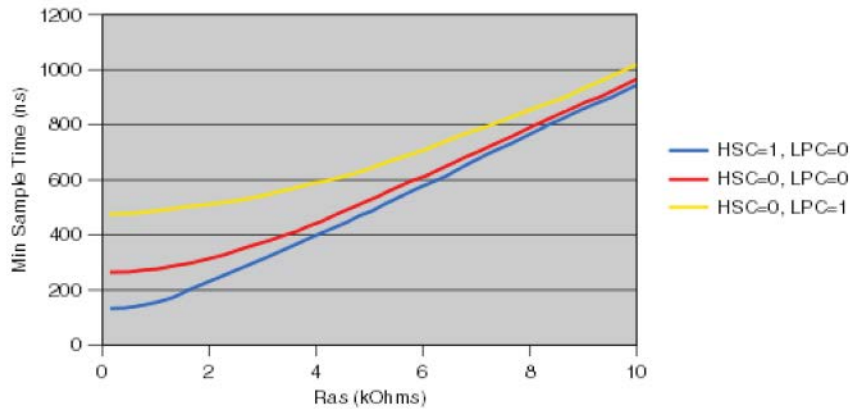


Figure 29. Minimum Sample Time Vs Ras (Cas = 5 pF)

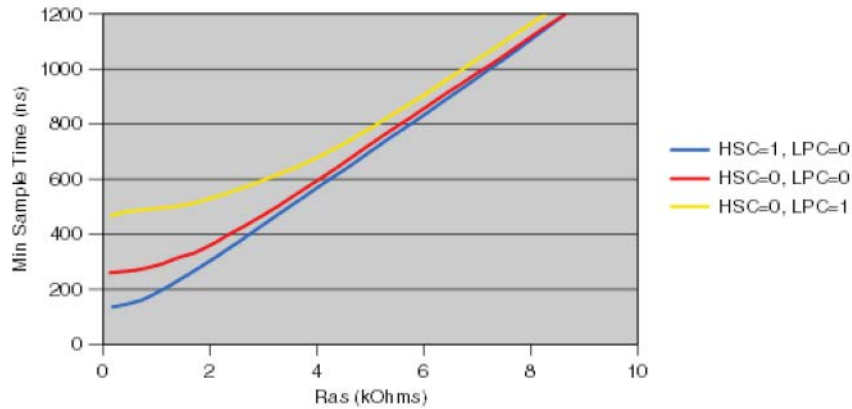


Figure 30. Minimum Sample Time Vs Ras (Cas = 10 pF)

4.8 Communication interfaces

The following sections provide the information about communication interfaces.

4.8.1 LPSPI timing parameters

The Low Power Serial Peripheral Interface (LPSPI) provides a synchronous serial bus with master and slave operations. Many of the transfer attributes are programmable. The following tables provide timing characteristics for classic LPSPI timing modes.

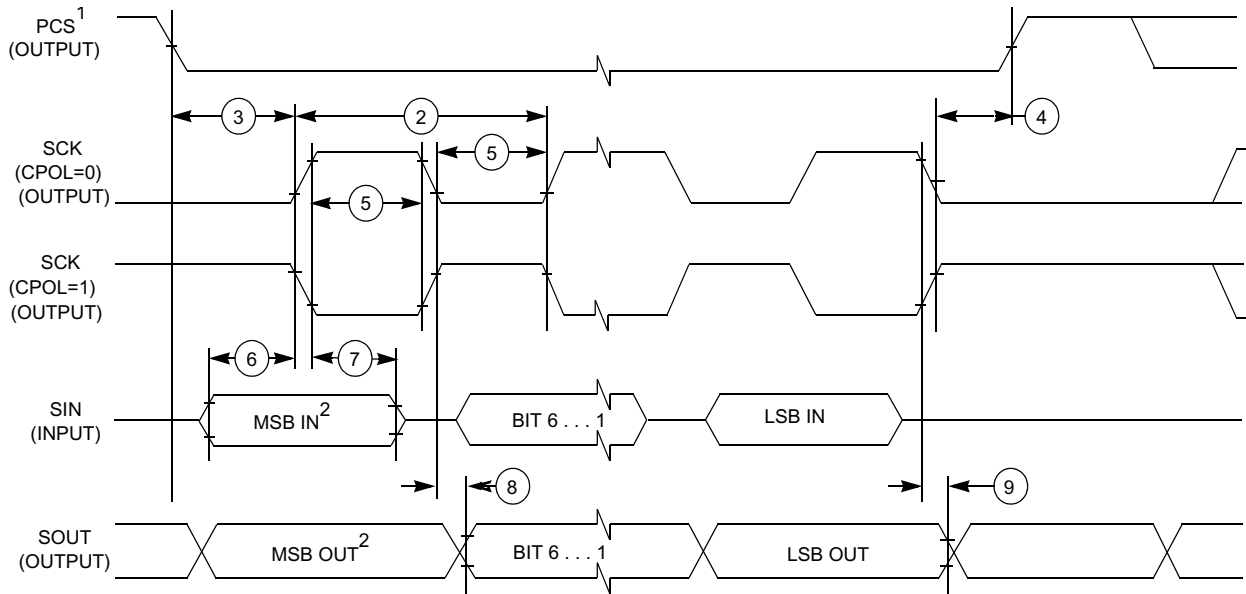
All timing is shown with respect to 20% V_{DD} and 80% V_{DD} thresholds, unless noted, as well as input signal transitions of 3 ns and a 30 pF maximum load on all LPSPI pins.

Table 45. LPSPI Master mode timing

| Number | Symbol | Description | Min. | Max. | Units | Note |
|--------|------------|------------------------------|-----------------------|------------------|--------------|--------------|
| 1 | f_{SCK} | Frequency of operation | — | $f_{periph} / 2$ | Hz | ¹ |
| 2 | t_{SCK} | SCK period | $2 \times t_{periph}$ | — | ns | ² |
| 3 | t_{Lead} | Enable lead time | 1 | — | t_{periph} | — |
| 4 | t_{Lag} | Enable lag time | 1 | — | t_{periph} | — |
| 5 | t_{WSCK} | Clock (SCK) high or low time | $t_{SCK} / 2 - 3$ | — | ns | — |
| 6 | t_{SU} | Data setup time (inputs) | 10 | — | ns | — |
| 7 | t_{HI} | Data hold time (inputs) | 2 | — | ns | — |
| 8 | t_V | Data valid (after SCK edge) | — | 8 | ns | — |
| 9 | t_{HO} | Data hold time (outputs) | 0 | — | ns | — |

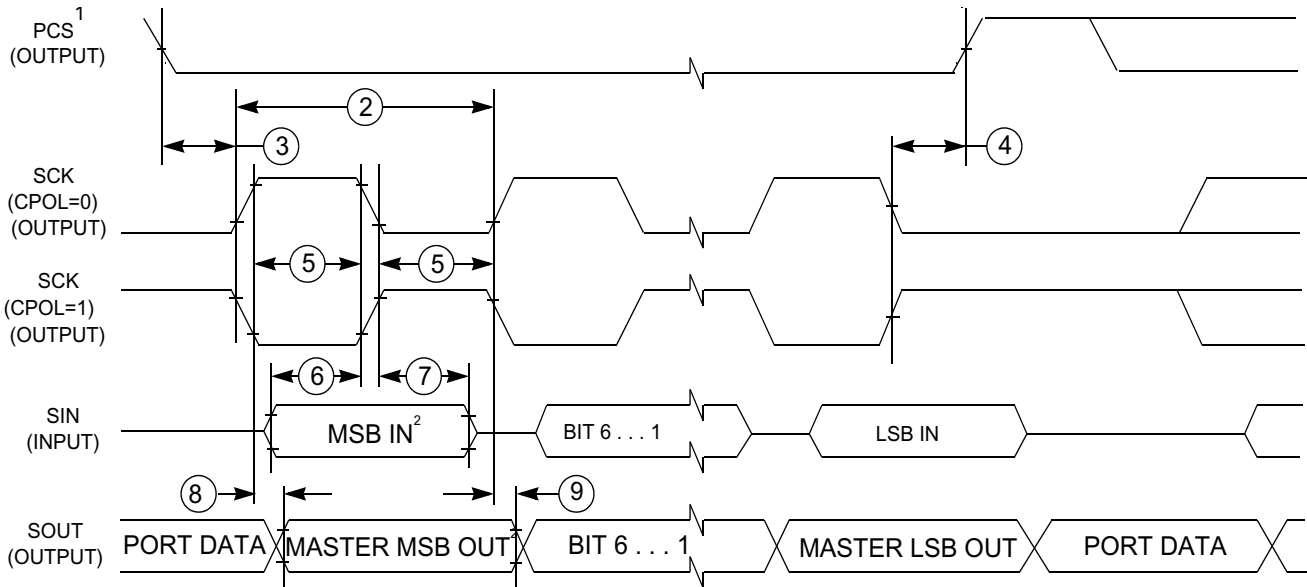
¹ Absolute maximum frequency of operation (fop) is 30 MHz. The clock driver in the LPSPI module for f_{periph} must be guaranteed this limit is not exceeded.

² $t_{periph} = 1 / f_{periph}$



- 1. If configured as an output.
- 2. LSBF = 0. For LSBF = 1, bit order is LSB, bit 1, ..., bit 6, MSB.

Figure 31. LPSPI Master mode timing (CPHA = 0)



- 1. If configured as output
- 2. LSBF = 0. For LSBF = 1, bit order is LSB, bit 1, ..., bit 6, MSB.

Figure 32. LPSPI Master mode timing (CPHA = 1)

Table 46. LPSPi Slave mode timing

| Number | Symbol | Description | Min. | Max. | Units | Note |
|--------|------------|------------------------------|-----------------------|------------------|--------------|------|
| 1 | f_{SCK} | Frequency of operation | 0 | $f_{periph} / 2$ | Hz | 1 |
| 2 | t_{SCK} | SCK period | $2 \times t_{periph}$ | — | ns | 2 |
| 3 | t_{Lead} | Enable lead time | 1 | — | t_{periph} | — |
| 4 | t_{Lag} | Enable lag time | 1 | — | t_{periph} | — |
| 5 | t_{WSCK} | Clock (SCK) high or low time | $t_{SCK} / 2 - 5$ | — | ns | — |
| 6 | t_{SU} | Data setup time (inputs) | 2.7 | — | ns | — |
| 7 | t_{HI} | Data hold time (inputs) | 3.8 | — | ns | — |
| 8 | t_a | Slave access time | — | t_{periph} | ns | 3 |
| 9 | t_{dis} | Slave MISO disable time | — | t_{periph} | ns | 4 |
| 10 | t_v | Data valid (after SCK edge) | — | 14.5 | ns | — |
| 11 | t_{HO} | Data hold time (outputs) | 0 | — | ns | — |

¹ Absolute maximum frequency of operation (fop) is 30 MHz. The clock driver in the LPSPi module for f_{periph} must be guaranteed this limit is not exceeded.

² $t_{periph} = 1 / f_{periph}$

³ Time to data active from high-impedance state

⁴ Hold time to high-impedance state

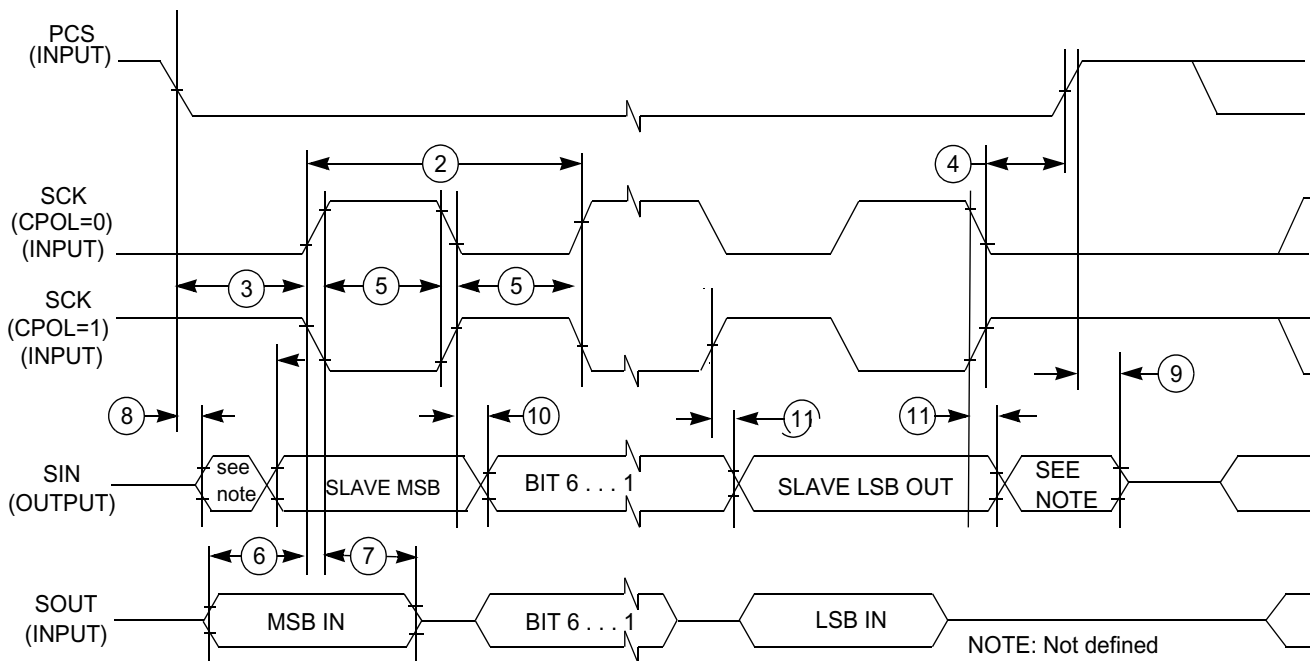


Figure 33. LPSPi Slave mode timing (CPHA = 0)

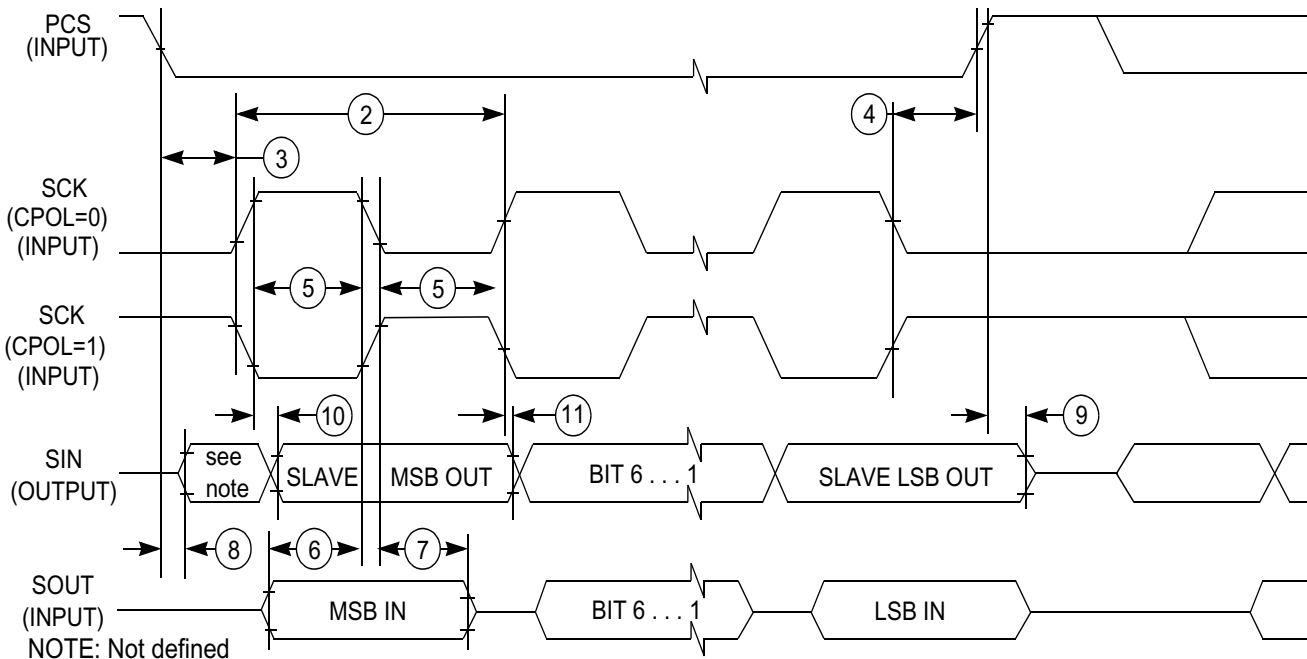


Figure 34. LPSPI Slave mode timing (CPHA = 1)

4.8.2 LPI2C module timing parameters

This section describes the timing parameters of the LPI2C module.

Table 47. LPI2C module timing parameters

| Symbol | Description | | Min | Max | Unit | Notes |
|-----------|---------------------|---------------------------|-----|------|------|-------|
| f_{SCL} | SCL clock frequency | Standard mode (Sm) | 0 | 100 | kHz | 1, 2 |
| | | Fast mode (Fm) | 0 | 400 | | |
| | | Fast mode Plus (Fm+) | 0 | 1000 | | |
| | | Ultra Fast mode (UFm) | 0 | 5000 | | |
| | | High speed mode (Hs-mode) | 0 | 3400 | | |

¹ Hs-mode is only supported in slave mode.

² See General switching specifications.

4.8.2.1 Bus operation condition for 3.3 V and 1.8 V signaling

Signaling level of SD/eMMC4.3 and eMMC4.4/4.41 modes is 3.3 V. Signaling level of SDR104/SDR50 mode is 1.8 V. The DC parameters for the NVCC_SD1 supply are identical to those shown in [Table 20](#), "Single voltage GPIO DC parameters," on page 27.

4.8.3 LPUART electrical specifications

Please refer to [Section 4.3.2.1, General purpose I/O AC parameters](#).

4.8.4 USB PHY parameters

This section describes the USB-OTG PHY parameters.

The USB PHY meets the electrical compliance requirements defined in the Universal Serial Bus Revision 2.0 OTG with the following amendments.

- USB ENGINEERING CHANGE NOTICE
 - Title: 5V Short Circuit Withstand Requirement Change
 - Applies to: Universal Serial Bus Specification, Revision 2.0
- Errata for USB Revision 2.0 April 27, 2000 as of 12/7/2000
- USB ENGINEERING CHANGE NOTICE
 - Title: Pull-up/Pull-down resistors
 - Applies to: Universal Serial Bus Specification, Revision 2.0
- USB ENGINEERING CHANGE NOTICE
 - Title: Suspend Current Limit Changes
 - Applies to: Universal Serial Bus Specification, Revision 2.0
- USB ENGINEERING CHANGE NOTICE
 - Title: USB 2.0 Phase Locked SOFs
 - Applies to: Universal Serial Bus Specification, Revision 2.0
- On-The-Go and Embedded Host Supplement to the USB Revision 2.0 Specification
 - Revision 2.0 plus errata and ecn June 4, 2010
- Battery Charging Specification (available from USB-IF)
 - Revision 1.2, December 7, 2010
 - Portable device only

4.9 Timers

This section provide information on timers.

4.9.1 Pulse Width Modulator (PWM) characteristics

This section describes the electrical information of the PWM.

Table 48. PWM timing parameters

| Parameter | Symbo | Min | Typ | Max | Unit |
|---------------------|----------|-----|-----|-----|---------|
| PWM Clock Frequency | — | 80 | — | 120 | MHz |
| Power-up Time | t_{pu} | — | 25 | — | μ s |

4.9.2 Quad timer timing

Table 49 listed the timing parameters.

Table 49. Quad Timer Timing

| Characteristic | Symbol | Min ¹ | Max | Unit | See Figure |
|------------------------------|-------------|------------------|-----|------|------------|
| Timer input period | T_{IN} | $2T + 6$ | — | ns | |
| Timer input high/low period | T_{INHL} | $1T + 3$ | — | ns | |
| Timer output period | T_{OUT} | 33 | — | ns | |
| Timer output high/low period | T_{OUTHL} | 16.7 | — | ns | |

¹ T = clock cycle. For 60 MHz operation, T = 16.7 ns.

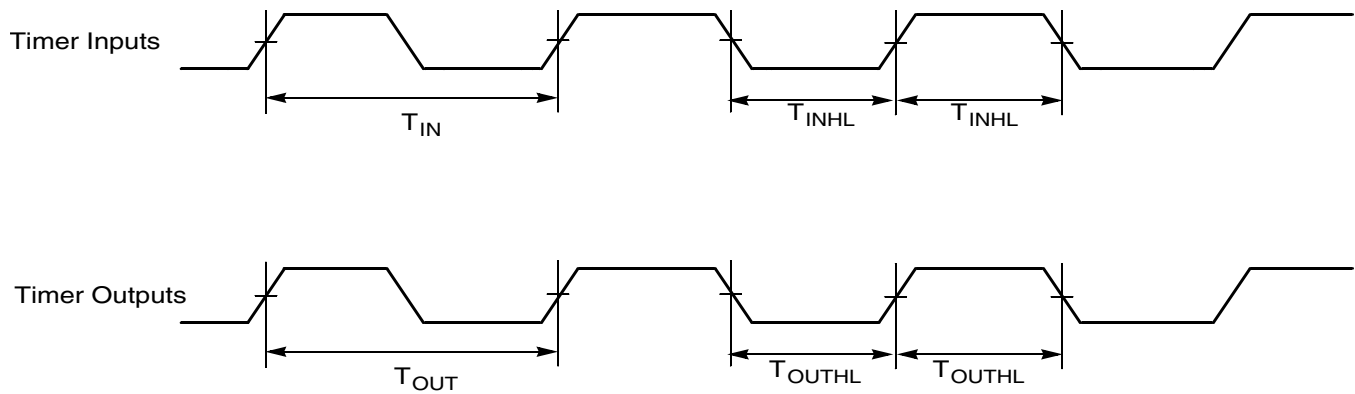


Figure 35. Quad timer timing

5 Boot mode configuration

This section provides information on boot mode configuration pins allocation and boot devices interfaces allocation.

5.1 Boot mode configuration pins

Table 50 provides boot options, functionality, fuse values, and associated pins. Several input pins are also sampled at reset and can be used to override fuse values, depending on the value of BT_FUSE_SEL fuse. The boot option pins are in effect when BT_FUSE_SEL fuse is '0' (cleared, which is the case for an unblown fuse). For detailed boot mode options configured by the boot mode pins, see the i.MX RT1015 Fuse Map document and the System Boot chapter in *i.MX RT1015 Reference Manual (IMXRT1015RM)*.

Table 50. Fuses and associated pins used for boot

| Pad | Default setting on reset | eFuse name | Details |
|-------------|--------------------------|----------------|--|
| GPIO_EMC_16 | 100 K pull-down | src.BOOT_MODE0 | |
| GPIO_EMC_17 | 100 K pull-down | src.BOOT_MODE1 | |
| GPIO_EMC_18 | 100 K pull-down | src.BT_CFG[0] | Boot Options, Pin value overrides fuse settings for BT_FUSE_SEL = '0'. Signal Configuration as Fuse Override Input at Power Up. These are special I/O lines that control the boot up configuration during product development. In production, the boot configuration can be controlled by fuses. |
| GPIO_EMC_19 | 100 K pull-down | src.BT_CFG[1] | |
| GPIO_EMC_20 | 100 K pull-down | src.BT_CFG[2] | |
| GPIO_EMC_21 | 100 K pull-down | src.BT_CFG[3] | |
| GPIO_EMC_22 | 100 K pull-down | src.BT_CFG[4] | |
| GPIO_EMC_23 | 100 K pull-down | src.BT_CFG[5] | |
| GPIO_EMC_24 | 100 K pull-down | src.BT_CFG[6] | |
| GPIO_EMC_25 | 100 K pull-down | src.BT_CFG[7] | |
| GPIO_EMC_26 | 100 K pull-down | src.BT_CFG[8] | |
| GPIO_EMC_27 | 100 K pull-down | src.BT_CFG[9] | |

5.2 Boot device interface allocation

The following tables list the interfaces that can be used by the boot process in accordance with the specific boot mode configuration. The tables also describe the interface's specific modes and IOMUXC allocation, which are configured during boot when appropriate.

Table 51. Boot through FlexSPI

| PAD Name | IO Function | Mux Mode | Comments |
|---------------|-------------------|----------|----------|
| GPIO_SD_B1_00 | flexspi.B_DATA[3] | ALT 1 | — |
| GPIO_SD_B1_03 | flexspi.B_DATA[2] | ALT 1 | — |
| GPIO_SD_B1_04 | flexspi.B_DATA[1] | ALT 1 | — |
| GPIO_SD_B1_02 | flexspi.B_DATA[0] | ALT 1 | — |

Table 51. Boot through FlexSPI (continued)

| PAD Name | IO Function | Mux Mode | Comments |
|---------------|-------------------|----------|----------|
| GPIO_SD_B1_01 | flexspi.B_SCLK | ALT 1 | — |
| GPIO_SD_B0_05 | flexspi.B_DQS | ALT 6 | — |
| GPIO_SD_B0_04 | flexspi.B_SS0_B | ALT 6 | — |
| GPIO_SD_B0_01 | flexspi.B_SS1_B | ALT 6 | — |
| GPIO_SD_B1_05 | flexspi.A_DQS | ALT 1 | — |
| GPIO_SD_B1_11 | flexspi.A_SS0_B | ALT 1 | — |
| GPIO_SD_B0_00 | flexspi.A_SS1_B | ALT 6 | — |
| GPIO_SD_B1_07 | flexspi.A_SCLK | ALT 1 | — |
| GPIO_SD_B1_08 | flexspi.A_DATA[0] | ALT 1 | — |
| GPIO_SD_B1_10 | flexspi.A_DATA[1] | ALT 1 | — |
| GPIO_SD_B1_09 | flexspi.A_DATA[2] | ALT 1 | — |
| GPIO_SD_B1_06 | flexspi.A_DATA[3] | ALT 1 | — |

Table 52. Boot through FlexSPI (second option)

| PAD Name | IO Function | Mux Mode | Comments |
|---------------|-------------------|----------|----------|
| GPIO_AD_B1_00 | flexspi.A_DATA[3] | ALT 1 | — |
| GPIO_AD_B1_01 | flexspi.A_SCLK | ALT 1 | — |
| GPIO_AD_B1_02 | flexspi.A_DATA[0] | ALT 1 | — |
| GPIO_AD_B1_03 | flexspi.A_DATA[2] | ALT 1 | — |
| GPIO_AD_B1_04 | flexspi.A_DATA[1] | ALT 1 | — |
| GPIO_AD_B1_05 | flexspi.A_SS0_B | ALT 1 | — |

Table 53. FlexSPI reset

| PAD Name | IO Function | Mux Mode | Comments |
|---------------|--------------|----------|----------|
| GPIO_AD_B1_13 | gpio1.IO[29] | ALT 5 | — |

Table 54. Boot through SPI-1

| PAD Name | IO Function | Mux Mode | Comments |
|---------------|-------------|----------|----------|
| GPIO_AD_B0_10 | lpspi1.SCK | ALT 1 | — |
| GPIO_AD_B0_11 | lpspi1.PCS0 | ALT 1 | — |
| GPIO_AD_B0_12 | lpspi1.SDO | ALT 1 | — |
| GPIO_AD_B0_13 | lpspi1.SDI | ALT 1 | — |

Boot mode configuration

Table 55. Boot through SPI-2

| PAD Name | IO Function | Mux Mode | Comments |
|---------------|-------------|----------|----------|
| GPIO_SD_B1_07 | lpspi2.SCK | ALT 4 | — |
| GPIO_SD_B1_08 | lpspi2.SDO | ALT 4 | — |
| GPIO_SD_B1_09 | lpspi2.SDI | ALT 4 | — |
| GPIO_SD_B1_06 | lpspi2.PCS0 | ALT 4 | — |

Table 56. Boot through UART1

| PAD Name | IO Function | Mux Mode | Comments |
|---------------|---------------|----------|----------|
| GPIO_AD_B0_06 | lpuart1.TX | ALT 2 | — |
| GPIO_AD_B0_07 | lpuart1.RX | ALT 2 | — |
| GPIO_AD_B0_08 | lpuart1.CTS_B | ALT 2 | — |
| GPIO_AD_B0_09 | lpuart1.RTS_B | ALT 2 | — |

Table 57. Boot through UART2

| PAD Name | IO Function | Mux Mode | Comments |
|---------------|---------------|----------|----------|
| GPIO_AD_B1_06 | lpuart2.CTS_B | ALT 2 | — |
| GPIO_AD_B1_07 | lpuart2.RTS_B | ALT 2 | — |
| GPIO_AD_B1_08 | lpuart2.TX | ALT 2 | — |
| GPIO_AD_B1_09 | lpuart2.RX | ALT 2 | — |

6 Package information and contact assignments

This section includes the contact assignment information and mechanical package drawing.

6.1 14 x 14 mm package information

6.1.1 14 x 14 mm, 0.5 mm pitch, ball matrix

[Figure 36](#) shows the top and side views of the 14 x 14 mm LQFP package.

Package information and contact assignments

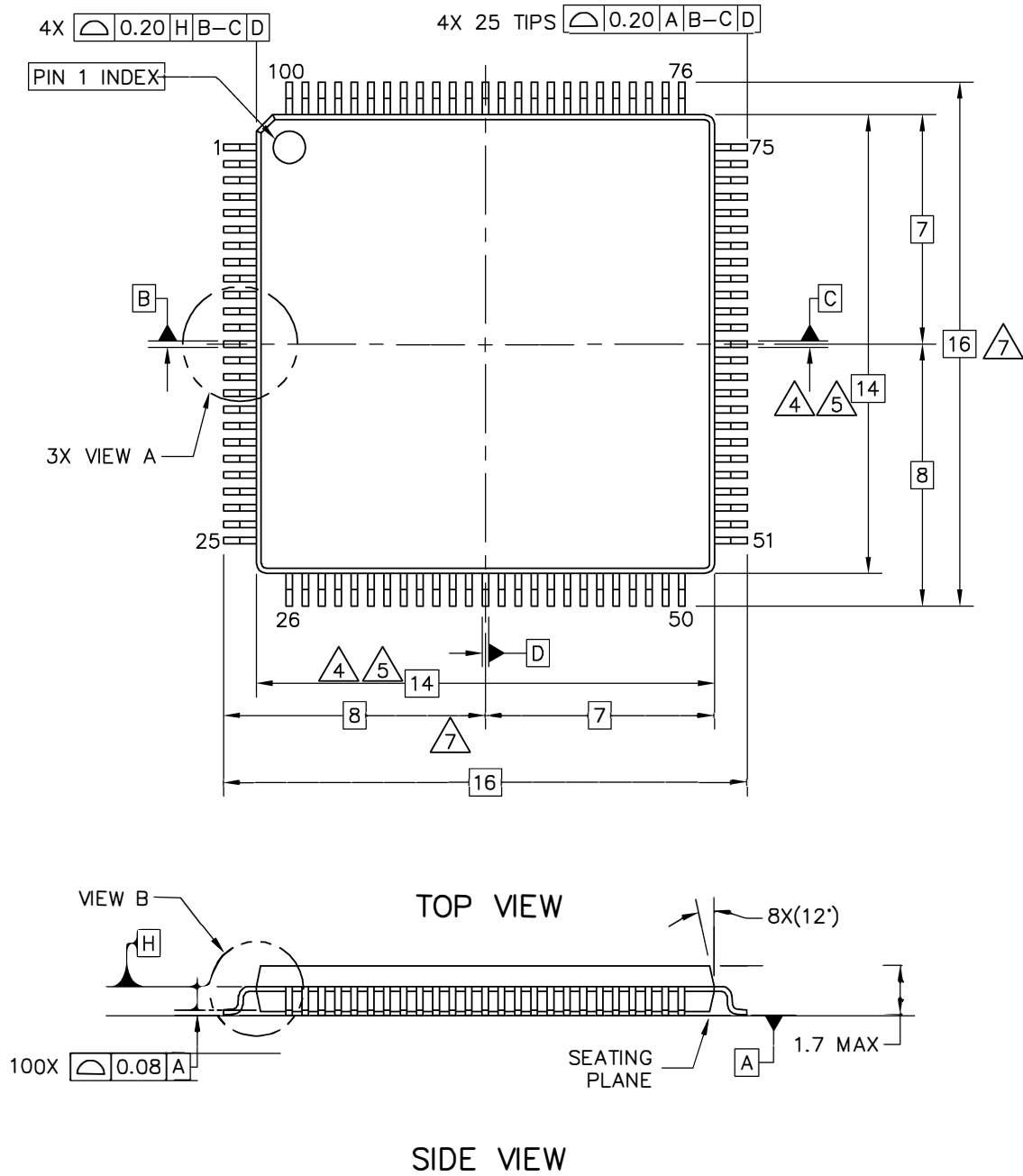


Figure 36. 14 x 14 mm LQFP, case x package top and side Views

6.1.2 14 x 14 mm supplies contact assignments and functional contact assignments

Table 58 shows the device connection list for ground, sense, and reference contact signals.

Table 58. 14 x 14 mm supplies contact assignment

| Supply Rail Name | Pin(s) Position(s) | Remark |
|------------------|--------------------------------|--------|
| DCDC_IN | 23 | — |
| DCDC_IN_Q | 27 | — |
| DCDC_GND | 24 | — |
| DCDC_LP | 25 | — |
| DCDC_PSWITCH | 26 | — |
| NVCC_GPIO | 5, 20, 58, 71, 80, 95 | — |
| NGND_KEL0 | 43 | — |
| NVCC_PLL | 50 | — |
| VDD_HIGH_CAP | 44 | — |
| VDD_HIGH_IN | 48 | — |
| VDD_SNVS_CAP | 35 | — |
| VDD_SNVS_IN | 34 | — |
| VDD_SOC_IN | 18, 28, 69, 81, 91 | — |
| VDD_USB_CAP | 40 | — |
| VDDA_ADC_3P3 | 51 | — |
| VSS | 19, 29, 39, 49, 59, 70, 79, 92 | — |

Table 59 shows an alpha-sorted list of functional contact assignments for the 14 x 14 mm package.

Table 59. 14 x 14 mm functional contact assignments

| Pin Name | 14 x 14 Pin | Power Group | Pin Type | Default Setting | | | |
|---------------|-------------|-------------|--------------|-----------------|------------------|--------------|----------|
| | | | | Default Mode | Default Function | Input/Output | Value |
| GPIO_AD_B0_00 | 78 | NVCC_GPIO | Digital GPIO | ALT0 | jtag_mux.TMS | Input | 47 K PU |
| GPIO_AD_B0_01 | 77 | NVCC_GPIO | Digital GPIO | ALT0 | jtag_mux.TCK | Input | 100 K PD |
| GPIO_AD_B0_02 | 76 | NVCC_GPIO | Digital GPIO | ALT0 | jtag_mux.MOD | Input | 100 K PD |
| GPIO_AD_B0_03 | 75 | NVCC_GPIO | Digital GPIO | ALT0 | jtag_mux.TDI | Input | 47 K PU |
| GPIO_AD_B0_04 | 74 | NVCC_GPIO | Digital GPIO | ALT0 | jtag_mux.TDO | Input | Keeper |

Table 59. 14 x 14 mm functional contact assignments (continued)

| | | | | | | | |
|--------------------------|----|-----------|--------------|------|----------------|-------|---------|
| GPIO_AD_B0_05 | 73 | NVCC_GPIO | Digital GPIO | ALT0 | jtag_mux.TRSTB | Input | 47 K PU |
| GPIO_AD_B0_06 | 72 | NVCC_GPIO | Digital GPIO | ALT5 | GPIO1.IO[6] | Input | Keeper |
| GPIO_AD_B0_07 | 68 | NVCC_GPIO | Digital GPIO | ALT5 | GPIO1.IO[7] | Input | Keeper |
| GPIO_AD_B0_08 | 67 | NVCC_GPIO | Digital GPIO | ALT5 | GPIO1.IO[8] | Input | Keeper |
| GPIO_AD_B0_09 | 66 | NVCC_GPIO | Digital GPIO | ALT5 | GPIO1.IO[9] | Input | Keeper |
| GPIO_AD_B0_10 | 65 | NVCC_GPIO | Digital GPIO | ALT5 | GPIO1.IO[10] | Input | Keeper |
| GPIO_AD_B0_11 | 64 | NVCC_GPIO | Digital GPIO | ALT5 | GPIO1.IO[11] | Input | Keeper |
| GPIO_AD_B0_12 | 63 | NVCC_GPIO | Digital GPIO | ALT5 | GPIO1.IO[12] | Input | Keeper |
| GPIO_AD_B0_13 | 62 | NVCC_GPIO | Digital GPIO | ALT5 | GPIO1.IO[13] | Input | Keeper |
| GPIO_AD_B0_14 | 61 | NVCC_GPIO | Digital GPIO | ALT5 | GPIO1.IO[14] | Input | Keeper |
| GPIO_AD_B0_15 | 60 | NVCC_GPIO | Digital GPIO | ALT5 | GPIO1.IO[15] | Input | Keeper |
| GPIO_AD_B1_10 | 57 | NVCC_GPIO | Digital GPIO | ALT5 | GPIO1.IO[26] | Input | Keeper |
| GPIO_AD_B1_11 | 56 | NVCC_GPIO | Digital GPIO | ALT5 | GPIO1.IO[27] | Input | Keeper |
| GPIO_AD_B1_12 | 55 | NVCC_GPIO | Digital GPIO | ALT5 | GPIO1.IO[28] | Input | Keeper |
| GPIO_AD_B1_13 | 54 | NVCC_GPIO | Digital GPIO | ALT5 | GPIO1.IO[29] | Input | Keeper |
| GPIO_AD_B1_14 | 53 | NVCC_GPIO | Digital GPIO | ALT5 | GPIO1.IO[30] | Input | Keeper |
| GPIO_AD_B1_15 | 52 | NVCC_GPIO | Digital GPIO | ALT5 | GPIO1.IO[31] | Input | Keeper |
| GPIO_EMC_04 ¹ | 7 | NVCC_GPIO | Digital GPIO | ALT5 | GPIO2.IO[4] | Input | Keeper |
| GPIO_EMC_05 | 6 | NVCC_GPIO | Digital GPIO | ALT5 | GPIO2.IO[5] | Input | Keeper |
| GPIO_EMC_06 | 4 | NVCC_GPIO | Digital GPIO | ALT5 | GPIO2.IO[6] | Input | Keeper |
| GPIO_EMC_07 | 3 | NVCC_GPIO | Digital GPIO | ALT5 | GPIO2.IO[7] | Input | Keeper |

Table 59. 14 x 14 mm functional contact assignments (continued)

| | | | | | | | |
|---------------|-----|-----------|--------------|------|------------------|-------|----------|
| GPIO_EMC_08 | 2 | NVCC_GPIO | Digital GPIO | ALT5 | GPIO2.IO[8] | Input | Keeper |
| GPIO_EMC_09 | 1 | NVCC_GPIO | Digital GPIO | ALT5 | GPIO2.IO[9] | Input | Keeper |
| GPIO_EMC_16 | 100 | NVCC_GPIO | Digital GPIO | ALT6 | src.BOOT_MODE[0] | Input | 100 k PD |
| GPIO_EMC_17 | 99 | NVCC_GPIO | Digital GPIO | ALT6 | src.BOOT_MODE[1] | Input | 100 k PD |
| GPIO_EMC_18 | 98 | NVCC_GPIO | Digital GPIO | ALT5 | GPIO2.IO[18] | Input | Keeper |
| GPIO_EMC_19 | 97 | NVCC_GPIO | Digital GPIO | ALT5 | GPIO2.IO[19] | Input | Keeper |
| GPIO_EMC_20 | 96 | NVCC_GPIO | Digital GPIO | ALT5 | GPIO2.IO[20] | Input | Keeper |
| GPIO_EMC_21 | 94 | NVCC_GPIO | Digital GPIO | ALT5 | GPIO2.IO[21] | Input | Keeper |
| GPIO_EMC_22 | 93 | NVCC_GPIO | Digital GPIO | ALT5 | GPIO2.IO[22] | Input | Keeper |
| GPIO_EMC_23 | 90 | NVCC_GPIO | Digital GPIO | ALT5 | GPIO2.IO[23] | Input | Keeper |
| GPIO_EMC_24 | 89 | NVCC_GPIO | Digital GPIO | ALT5 | GPIO2.IO[24] | Input | Keeper |
| GPIO_EMC_25 | 88 | NVCC_GPIO | Digital GPIO | ALT5 | GPIO2.IO[25] | Input | Keeper |
| GPIO_EMC_26 | 87 | NVCC_GPIO | Digital GPIO | ALT5 | GPIO2.IO[26] | Input | Keeper |
| GPIO_EMC_27 | 86 | NVCC_GPIO | Digital GPIO | ALT5 | GPIO2.IO[27] | Input | Keeper |
| GPIO_EMC_32 | 85 | NVCC_GPIO | Digital GPIO | ALT5 | GPIO3.IO[0] | Input | Keeper |
| GPIO_EMC_33 | 84 | NVCC_GPIO | Digital GPIO | ALT5 | GPIO3.IO[1] | Input | Keeper |
| GPIO_EMC_34 | 83 | NVCC_GPIO | Digital GPIO | ALT5 | GPIO3.IO[2] | Input | Keeper |
| GPIO_EMC_35 | 82 | NVCC_GPIO | Digital GPIO | ALT5 | GPIO3.IO[3] | Input | Keeper |
| GPIO_SD_B1_00 | 22 | NVCC_GPIO | Digital GPIO | ALT5 | GPIO3.IO[20] | Input | Keeper |
| GPIO_SD_B1_01 | 21 | NVCC_GPIO | Digital GPIO | ALT5 | GPIO3.IO[21] | Input | Keeper |
| GPIO_SD_B1_02 | 17 | NVCC_GPIO | Digital GPIO | ALT5 | GPIO3.IO[22] | Input | Keeper |

Table 59. 14 x 14 mm functional contact assignments (continued)

| | | | | | | | |
|----------------|----|-------------|--------------|------|---------------------|--------|----------|
| GPIO_SD_B1_03 | 16 | NVCC_GPIO | Digital GPIO | ALT5 | GPIO3.IO[23] | Input | Keeper |
| GPIO_SD_B1_04 | 15 | NVCC_GPIO | Digital GPIO | ALT5 | GPIO3.IO[24] | Input | Keeper |
| GPIO_SD_B1_05 | 14 | NVCC_GPIO | Digital GPIO | ALT5 | GPIO3.IO[25] | Input | Keeper |
| GPIO_SD_B1_06 | 13 | NVCC_GPIO | Digital GPIO | ALT5 | GPIO3.IO[26] | Input | Keeper |
| GPIO_SD_B1_07 | 12 | NVCC_GPIO | Digital GPIO | ALT5 | GPIO3.IO[27] | Input | Keeper |
| GPIO_SD_B1_08 | 11 | NVCC_GPIO | Digital GPIO | ALT5 | GPIO3.IO[28] | Input | Keeper |
| GPIO_SD_B1_09 | 10 | NVCC_GPIO | Digital GPIO | ALT5 | GPIO3.IO[29] | Input | Keeper |
| GPIO_SD_B1_10 | 9 | NVCC_GPIO | Digital GPIO | ALT5 | GPIO3.IO[30] | Input | Keeper |
| GPIO_SD_B1_11 | 8 | NVCC_GPIO | Digital GPIO | ALT5 | GPIO3.IO[31] | Input | Keeper |
| ONOFF | 30 | VDD_SNVS_IN | Digital GPIO | ALT0 | src.RESET_B | Input | 100 K PU |
| PMIC_ON_REQ | 33 | VDD_SNVS_IN | Digital GPIO | ALT0 | snvs_lp.PMIC_ON_REQ | Input | 100 K PU |
| POR_B | 31 | VDD_SNVS_IN | Digital GPIO | ALT0 | src.POR_B | Output | 100 K PU |
| RTC_XTALI | 36 | — | — | — | — | — | — |
| RTC_XTALO | 37 | — | — | — | — | — | — |
| TEST_MODE | 32 | VDD_SNVS_IN | Digital GPIO | ALT0 | tcu.TEST_MODE | Input | 100 K PD |
| USB_OTG1_CHD_B | 45 | — | — | — | — | — | — |
| USB_OTG1_DN | 41 | — | — | — | — | — | — |
| USB_OTG1_DP | 42 | — | — | — | — | — | — |
| USB_OTG1_VBUS | 38 | — | — | — | — | — | — |
| XTALI | 46 | — | — | — | — | — | — |
| XTALO | 47 | — | — | — | — | — | — |

¹ This pin output is in a high level until the system reset is complete.

6.1.3 14 x 14 mm package pin assignments

Figure 37 shows the pin assignments of the 14 x 14 mm package.

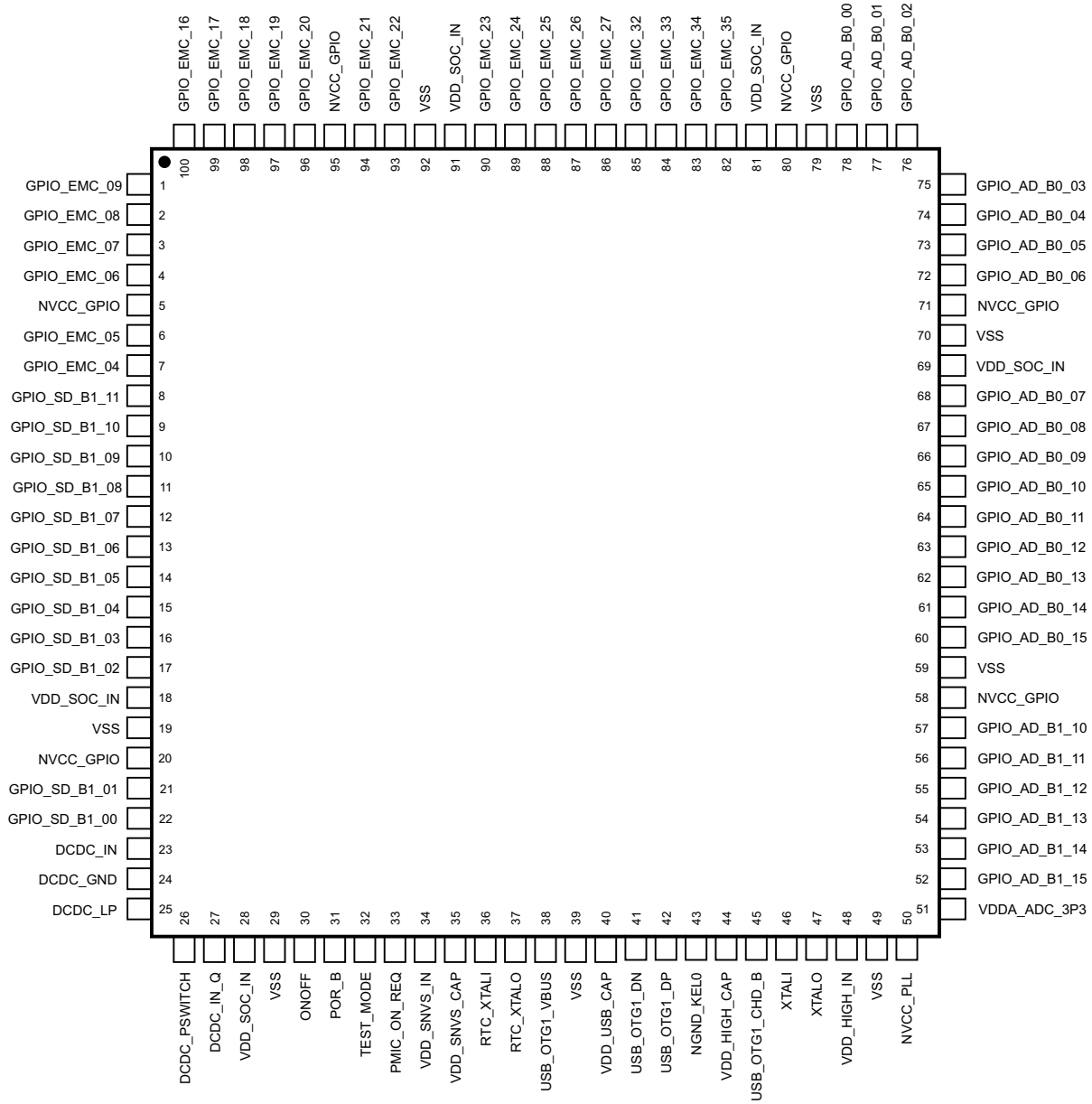


Figure 37. The pin assignments of the 14 x 14 mm package

7 Revision history

Table 60 provides a revision history for this data sheet.

Table 60. i.MX RT1015 data sheet document revision history

| Rev. Number | Date | Substantive Change(s) |
|-------------|---------|---|
| Rev. 3.1 | 03/2022 | <ul style="list-style-type: none"> Updated the back page information |
| Rev. 3 | 08/2021 | <ul style="list-style-type: none"> Added new part numbers for silicon Rev B in the Section 1.2, Ordering information |
| Rev. 2 | 03/2021 | <ul style="list-style-type: none"> Updated the M7 Core and external memory descriptions in the Section 1.1, Features Updated the Figure 1, "Part number nomenclature—i.MX RT10XX family" Updated the frequency of RTC OSC and baud rates of LPUART in the Table 2, i.MX RT1015 modules list Updated the descriptions about TEST_MODE in the Table 3, Special signal considerations Added system and bus frequencies in the Table 9, Operating ranges; updated the junction temperature descriptions in the Table 9, Operating ranges Updated the test conditions and max current of DCDC_IN in the Table 11, Maximum supply currents Added a note in the Section 4.2.1.1, Power-up sequence Updated the value of reference clock in the Table 16, Ethernet PLL's electrical parameters Added the high-level and low-level output current in the Table 20, Single voltage GPIO DC parameters Added a footnote for GPIO_EMC_04 in the Table 59, 14 x 14 mm functional contact assignments |
| Rev. 1 | 04/2019 | <ul style="list-style-type: none"> Updated the SNVS descriptions in the Table 2, i.MX RT1015 modules list Updated the Section 4.8.1, LPSPI timing parameters |
| Rev. 0.1 | 03/2019 | <ul style="list-style-type: none"> Added audio information and updated the frequency in the Section 1, i.MX RT1015 introduction Updated FlexPWMs, core frequency, Quadrature Encoder/Decoder in the Section 1.1, Features Updated the Table 1, Ordering information Updated keypad and GP timer numbers in the Figure 2, "i.MX RT1015 system block diagram" Changed keypad to 4 x 4 in the Table 2, i.MX RT1015 modules list Removed the USB OTG2 from the Table 2, i.MX RT1015 modules list, Table 7, Absolute maximum ratings, and Section 4.2.1.1, Power-up sequence Updated on-chip termination information for the JTAG_TCK and JTAG_MOD in the Table 4, JTAG controller interface summary Updated descriptions in the Section 4.2.2.3, LDO_USB Changed the 528 MHz PLL to System PLL in the Table 15, System PLL's electrical parameters Changed the 480 MHz PLL to USB PLL in the Table 17, USB PLL's electrical parameters |
| Rev. 0 | 01/2019 | <ul style="list-style-type: none"> Initial version |

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Data sheet status

| Document status ^{[1][2]} | Product status ^[3] | Definition |
|-----------------------------------|-------------------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
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Date of release: 03/2022

Document identifier: IMXRT1015IEC

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